

Additive Manufacturing – Module 11

Spring 2015

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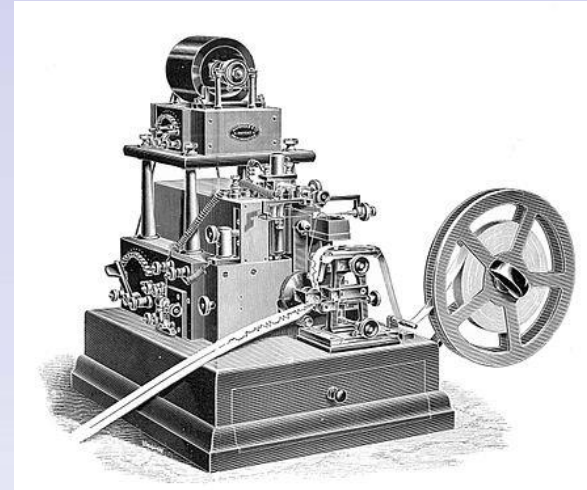
(479) 575-7250

The Department of Mechanical Engineering
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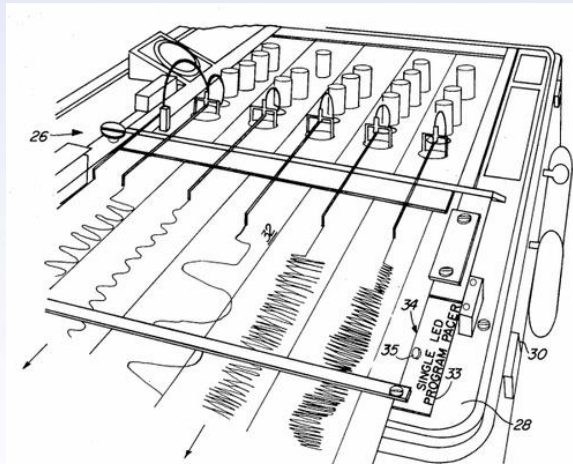
History



Syringe



1867 Lord Kelvin: Syphon recorder
Continuous inkjet



1951: Chart recorder -- Siemens
Continuous inkjet



1970s: Desktop printer
DOD inkjet



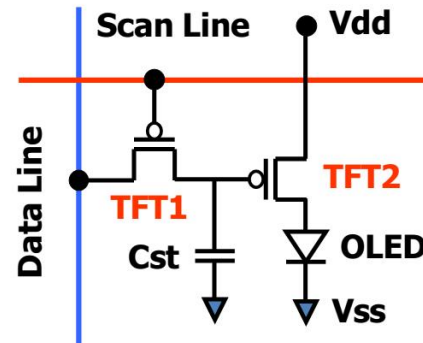
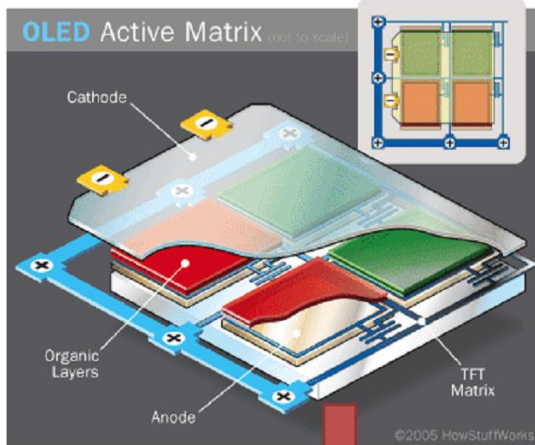
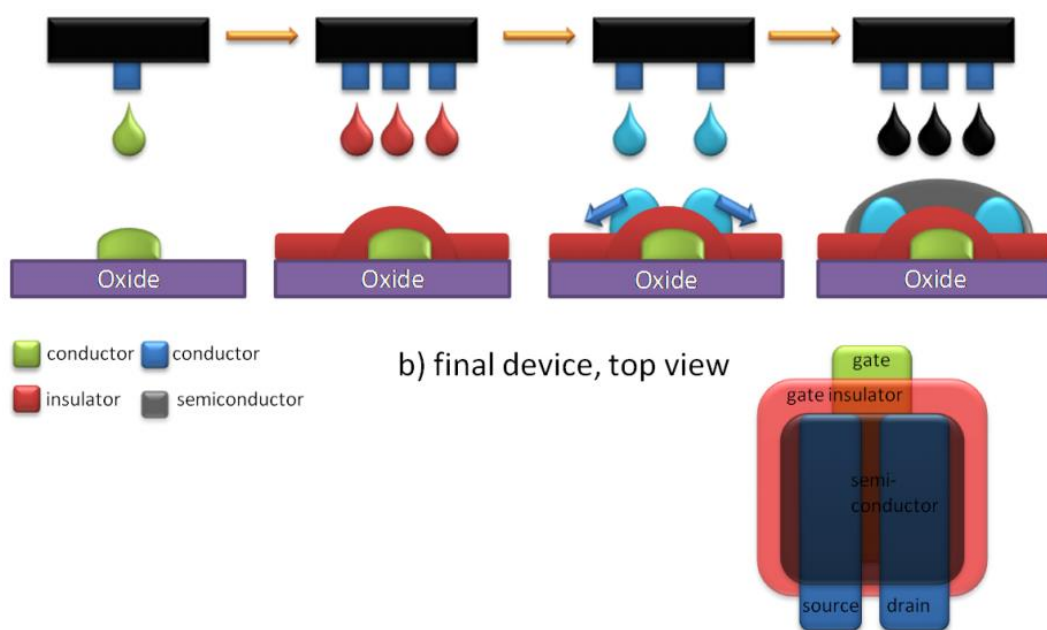
1990s: 3D printer
DOD inkjet

Inkjet Deposition

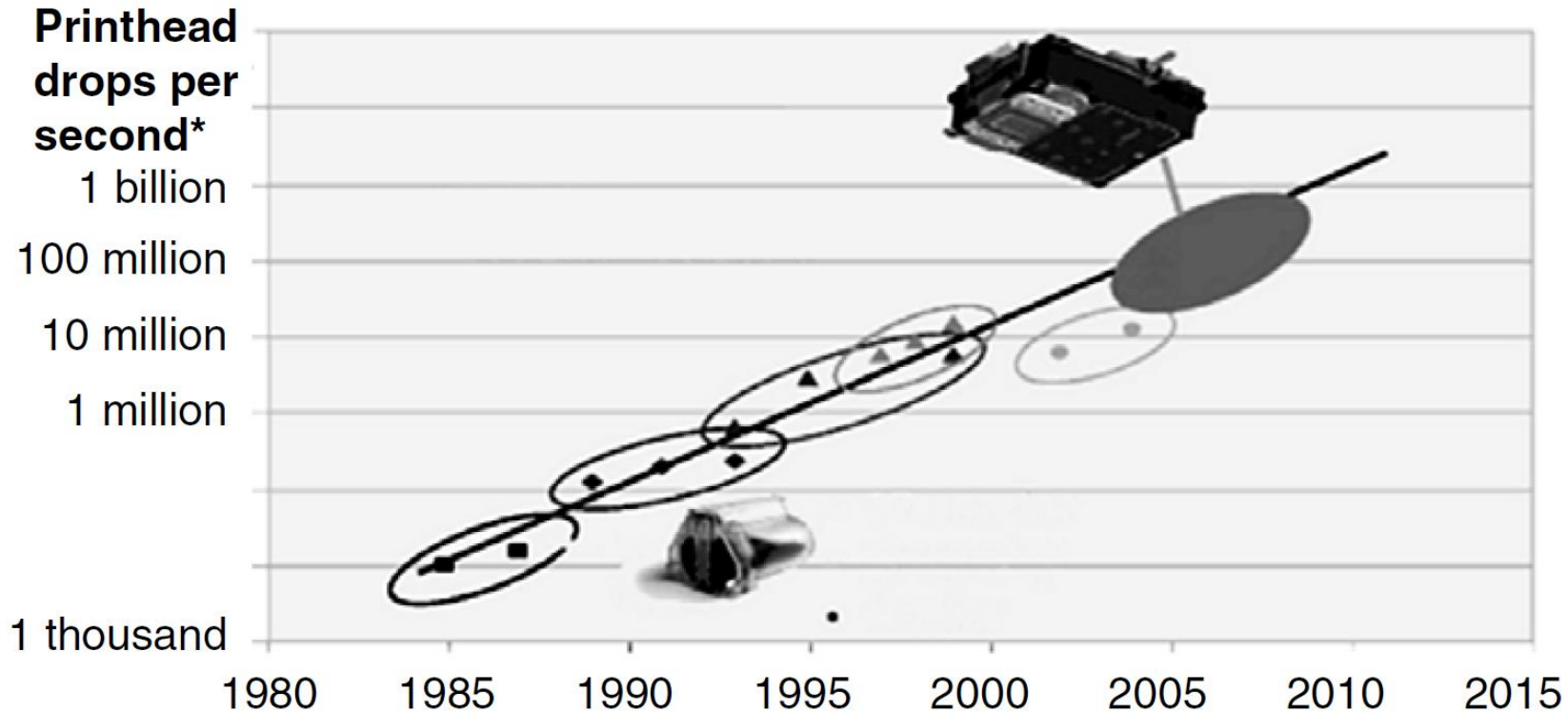
❖ Commercial Engagement



Applications



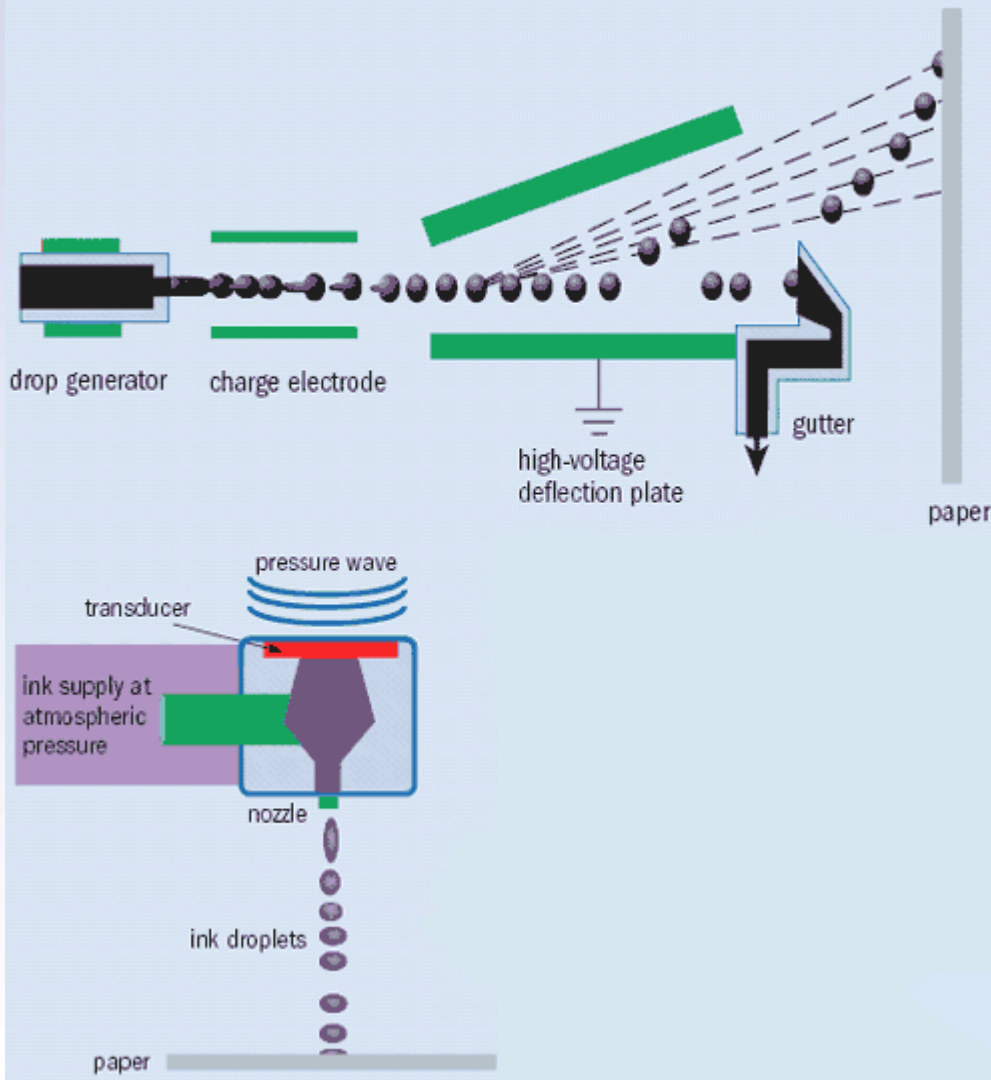
◆ HP Moore's Law



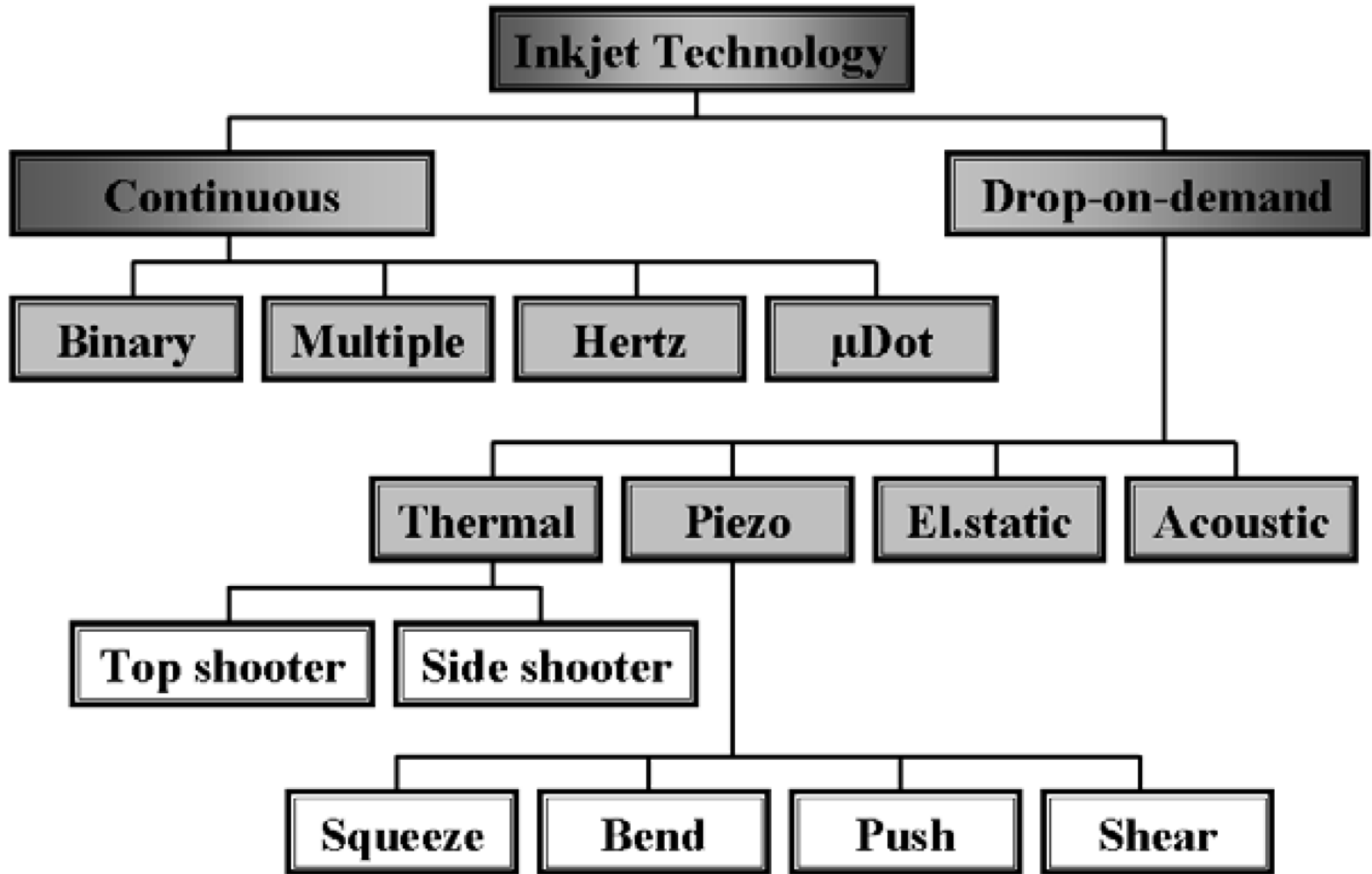
HP Moore's law: inkjet printhead performance as printhead drops per second (the number of nozzles times the maximum drop-on-demand frequency) doubles every 18 months for the past 20 years.

Types of inkjet

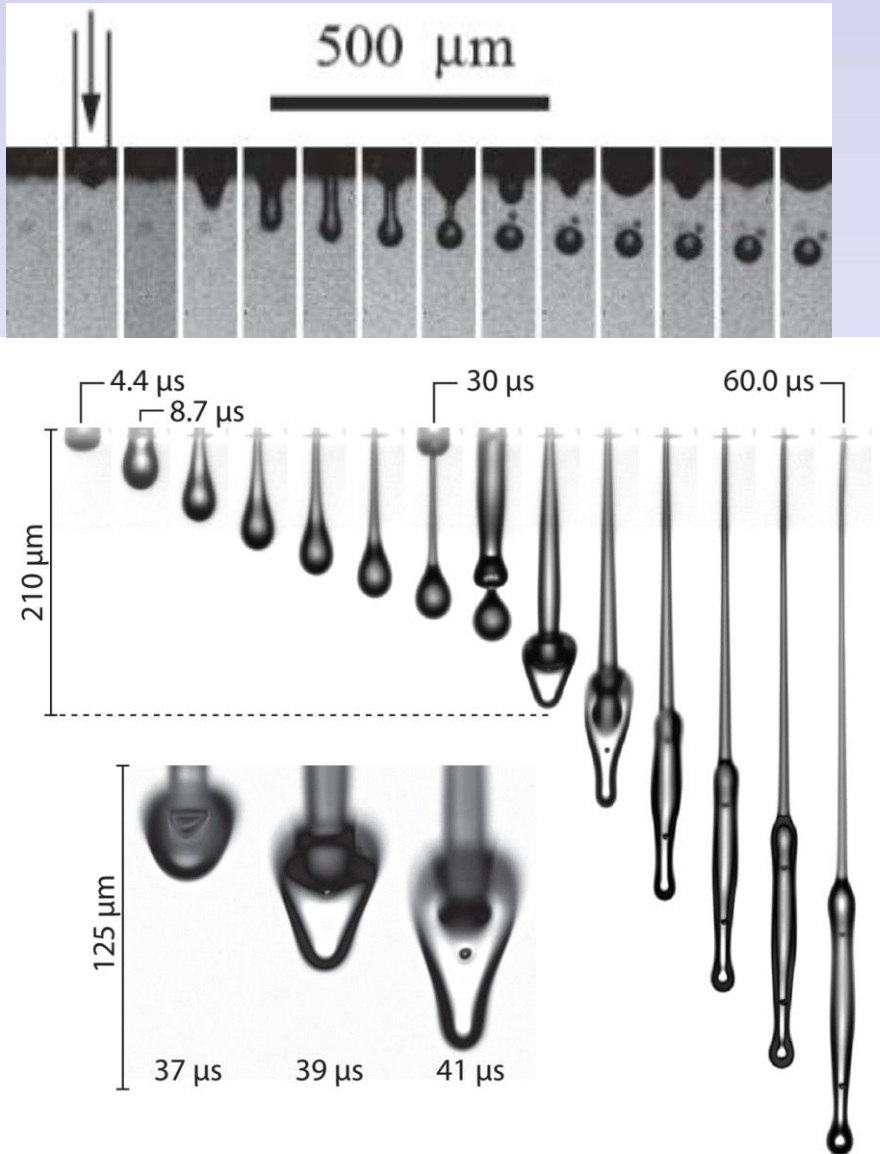
2 The two types of ink-jet technology



❖ Complexities – Jetting



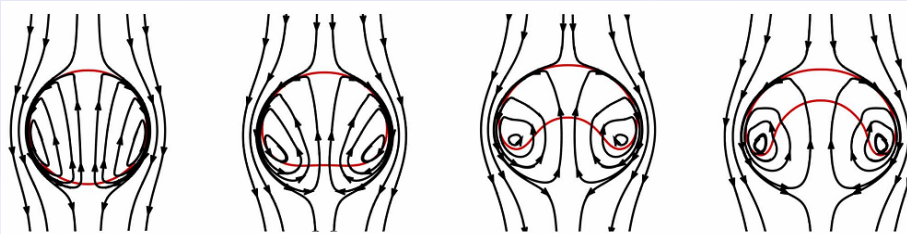
❖ Complexities – Drop Formation



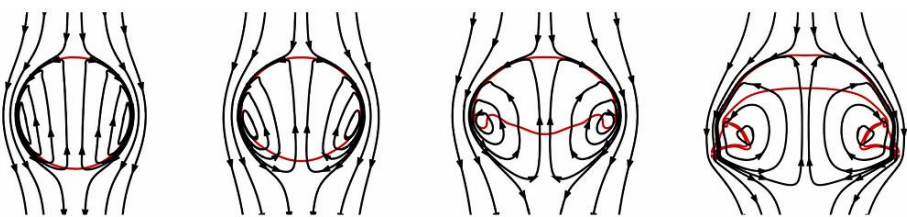
❖ Complexities – Falling



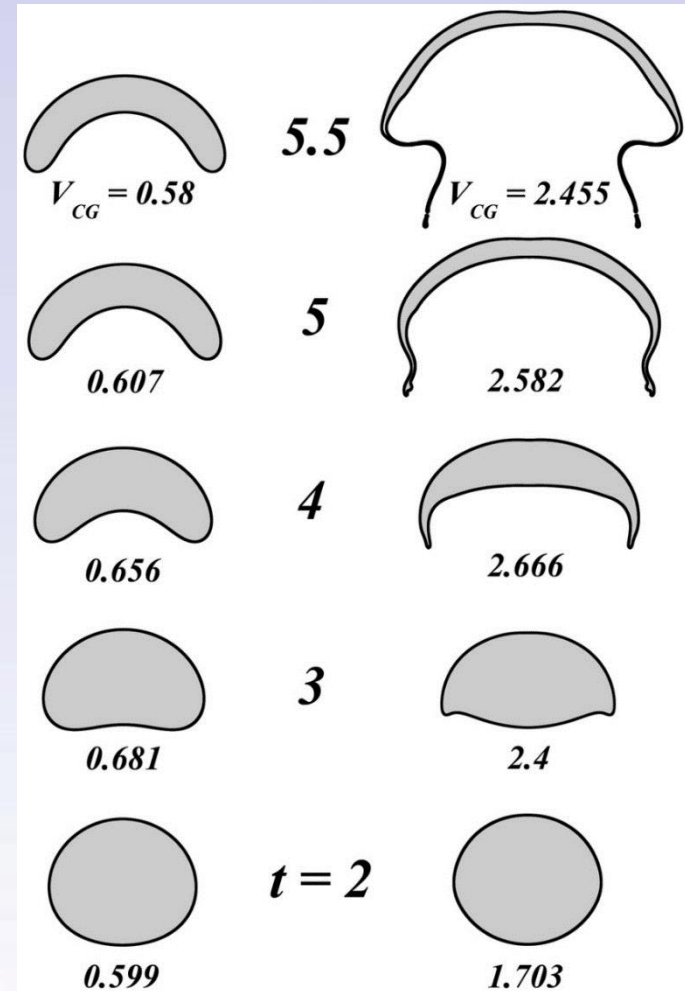
Falling droplets



Streamlines in the vicinity of a bubble. The shape of the bubble is plotted in red.

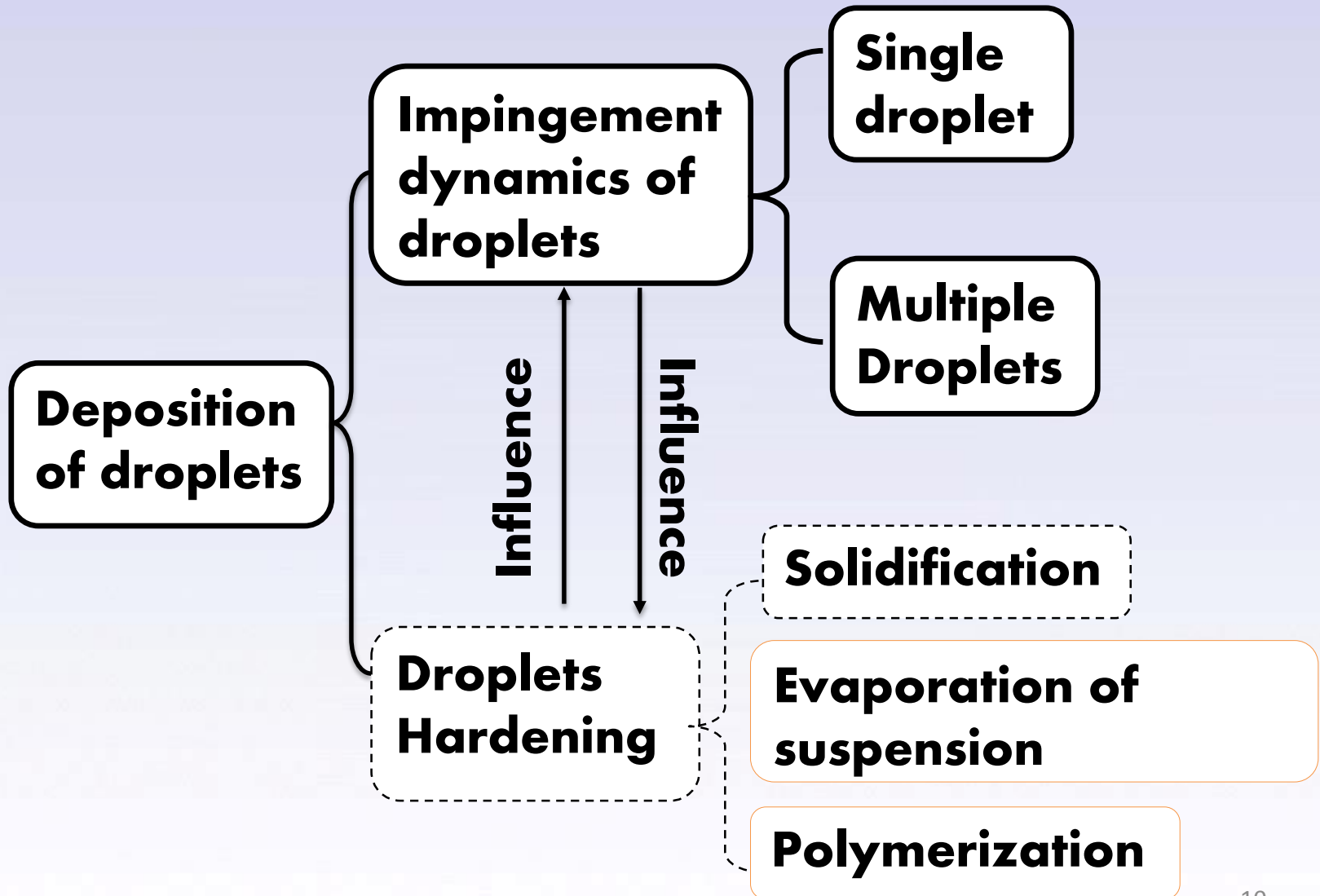


Streamlines in the vicinity of a drop The shape of the drop is plotted in red.



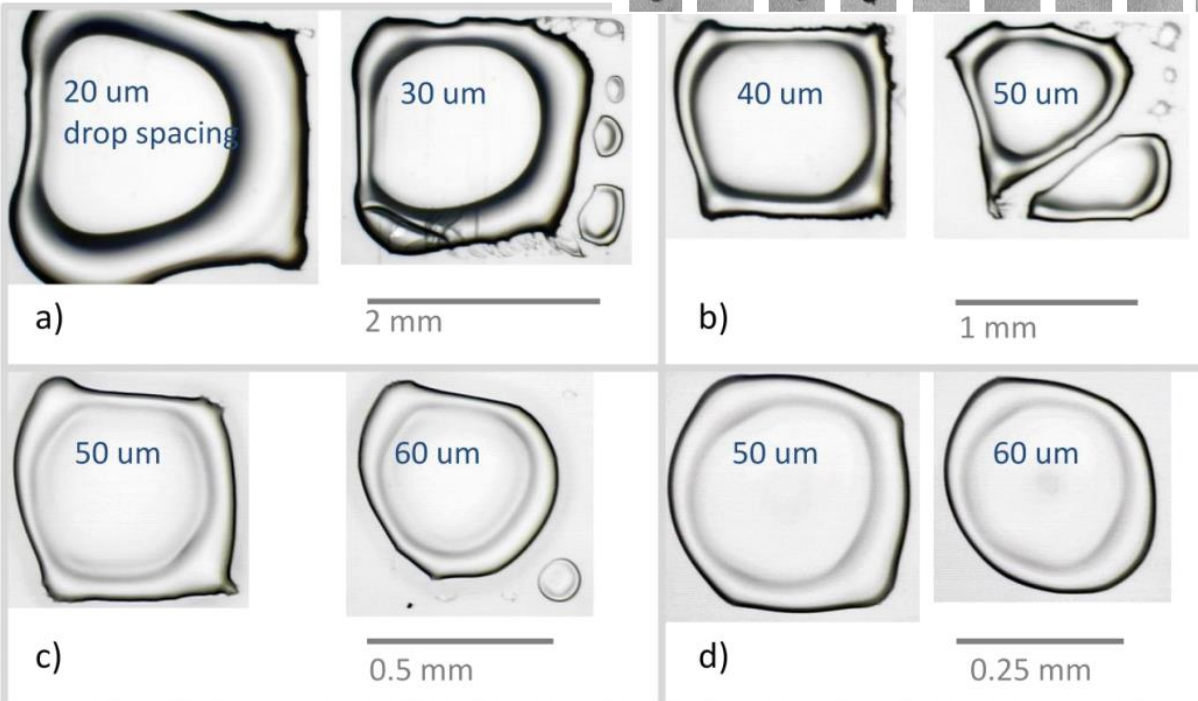
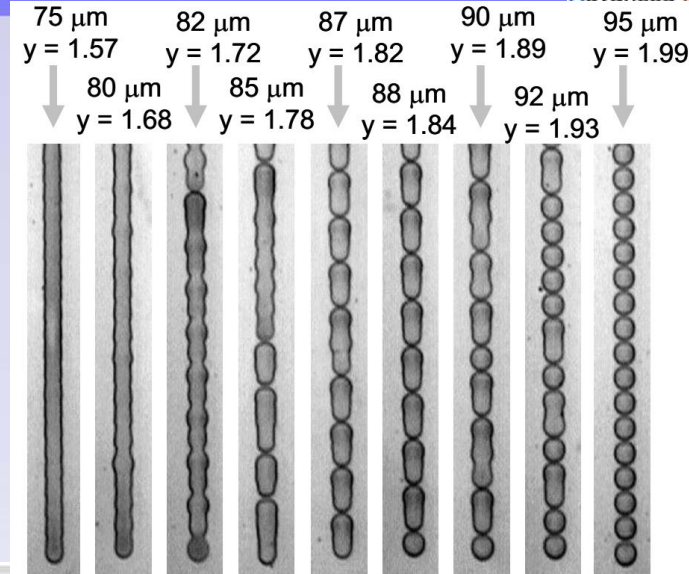
Evolution of (a) bubble and (b) drop (gravity reversed) shapes with time.

❖ Complexities – Droplet deposition

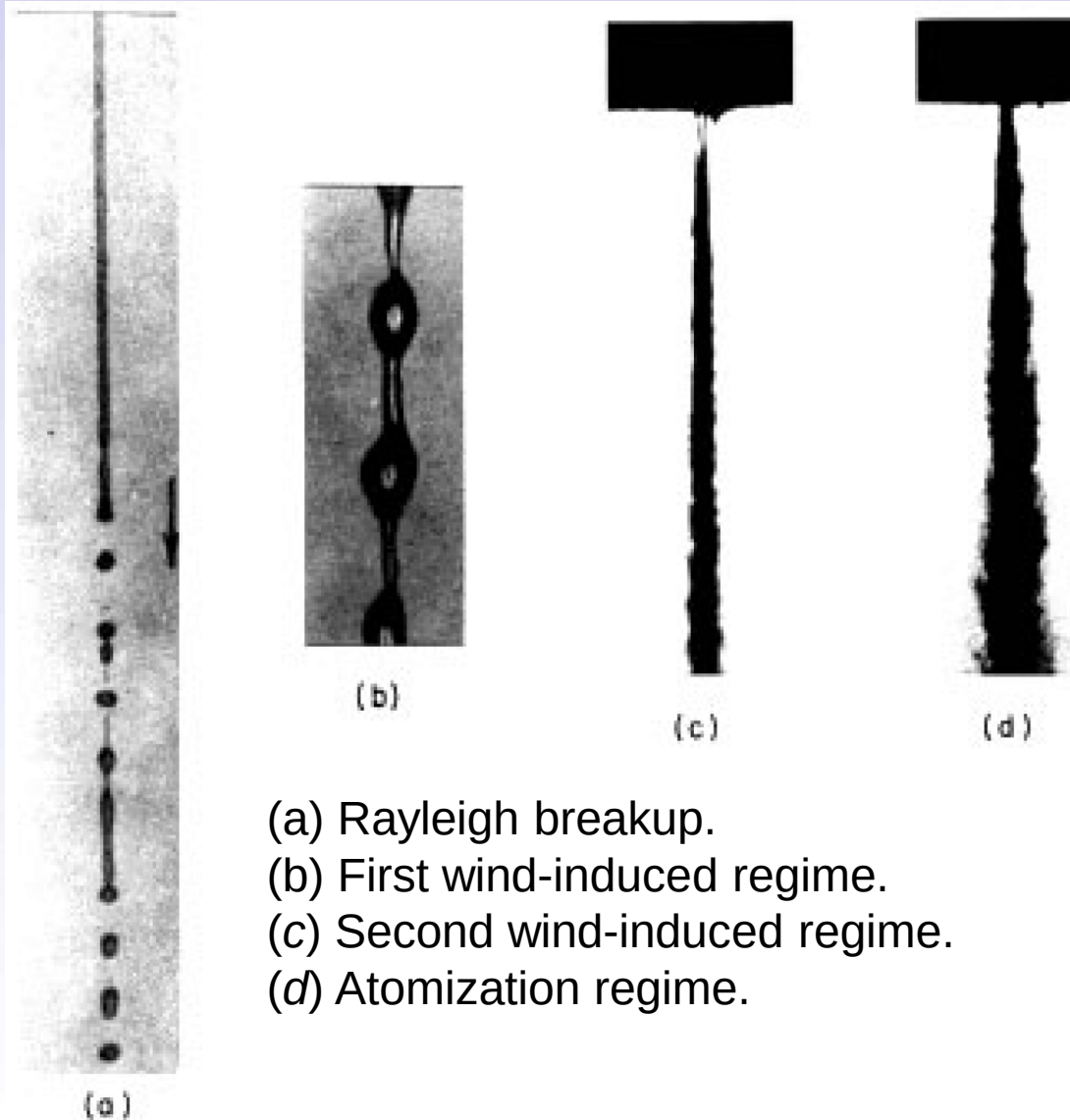


Inkjet Deposition

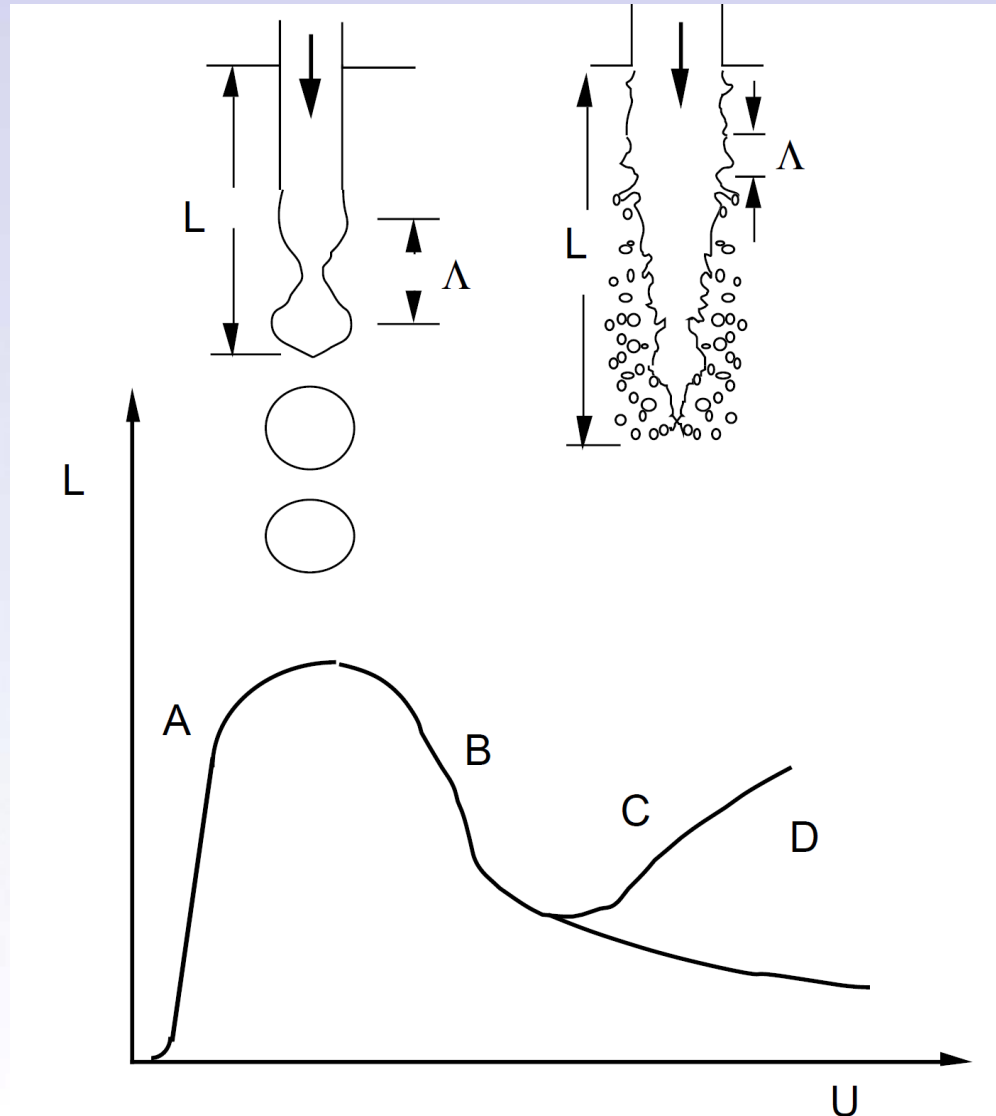
Complexities



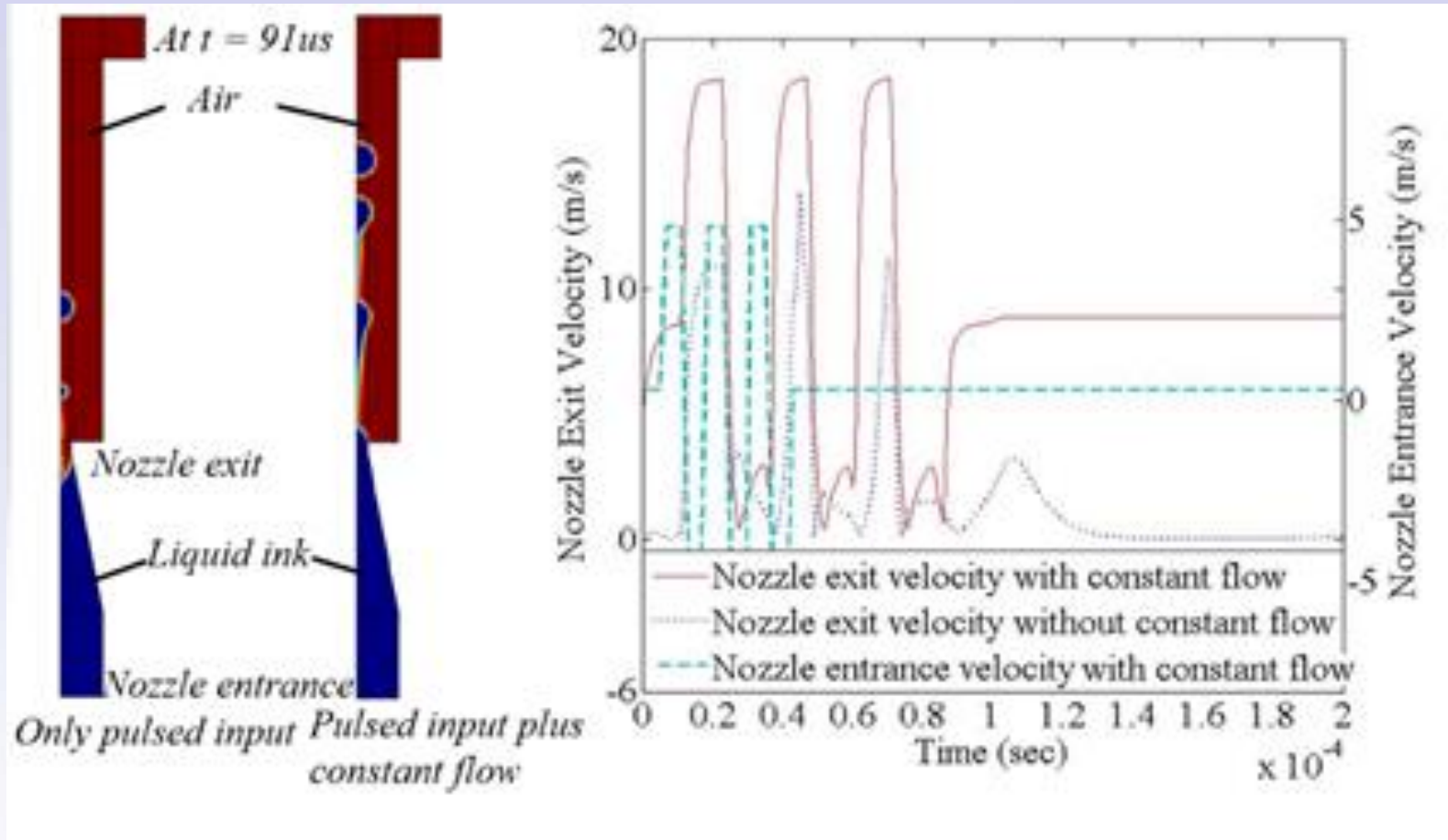
◆ Droplet formation



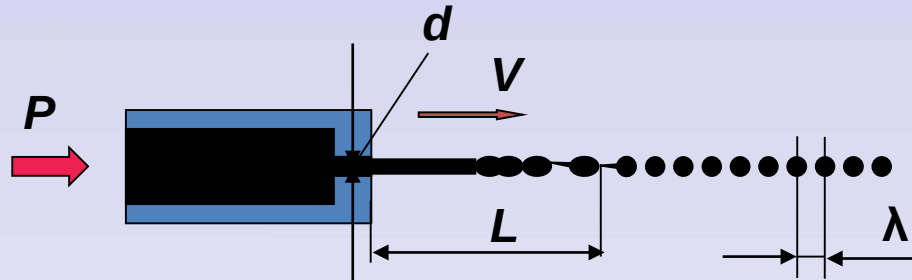
◆ Droplet formation



❖ Droplet formation



Continuous inkjet



Emerging from an orifice liquid jet breaks-up into droplets. Because of the surface tension:

- Droplets have random size
- Droplets have random spacing

α_0 – the initial disturbance

ρ - the density of the fluid

σ – the surface tension of the fluid

L – break-up length

f_s – the frequency of spontaneous drop formation

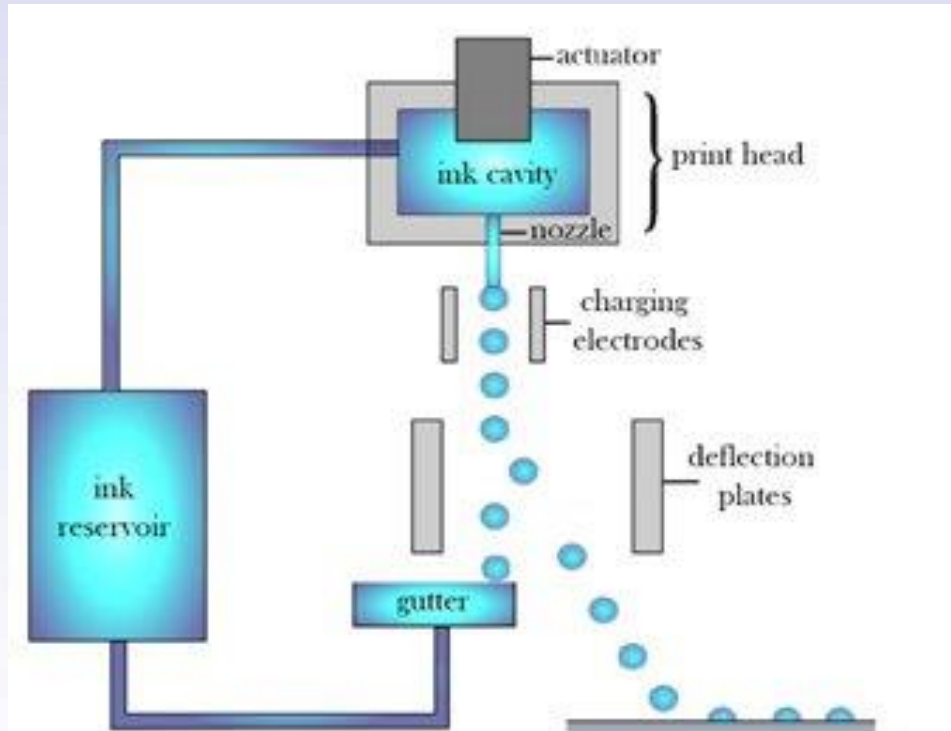
λ – wave length

$$L = K \ln(d/2\alpha_0) V (\rho d^3 / \sigma)^{0.5}$$

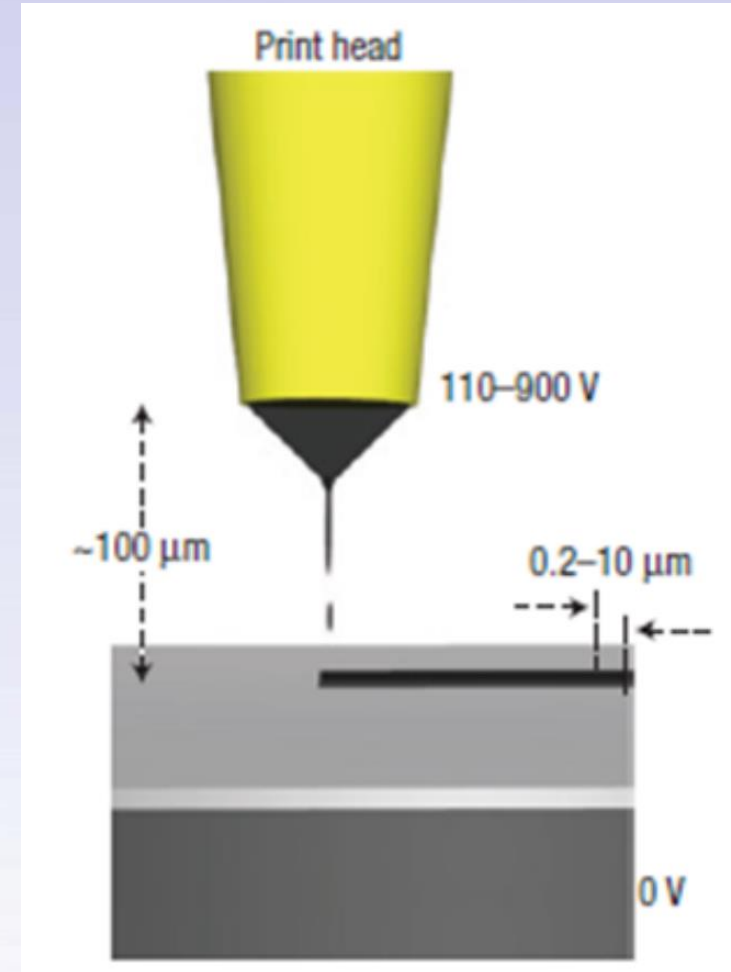
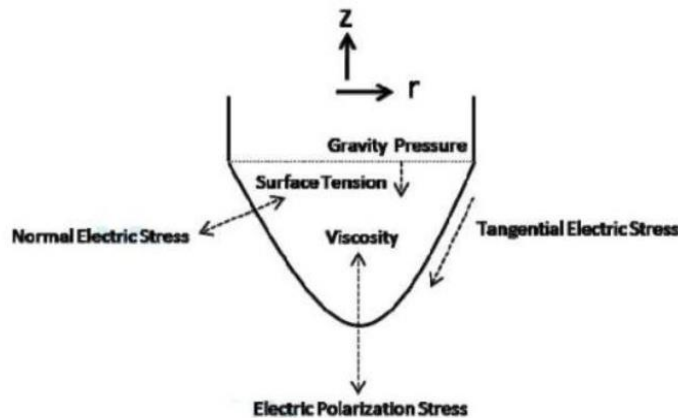
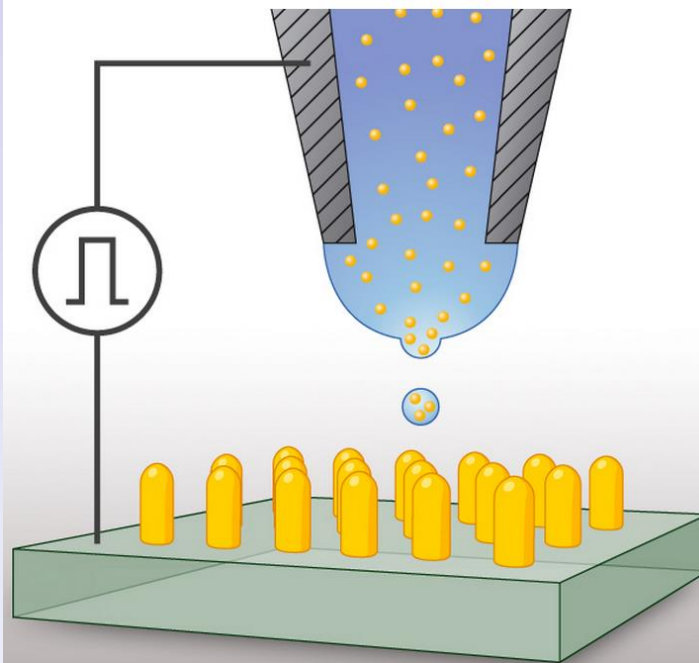
$$\lambda = 4.51d; f_s = V/4.51d$$

Continuous inkjet

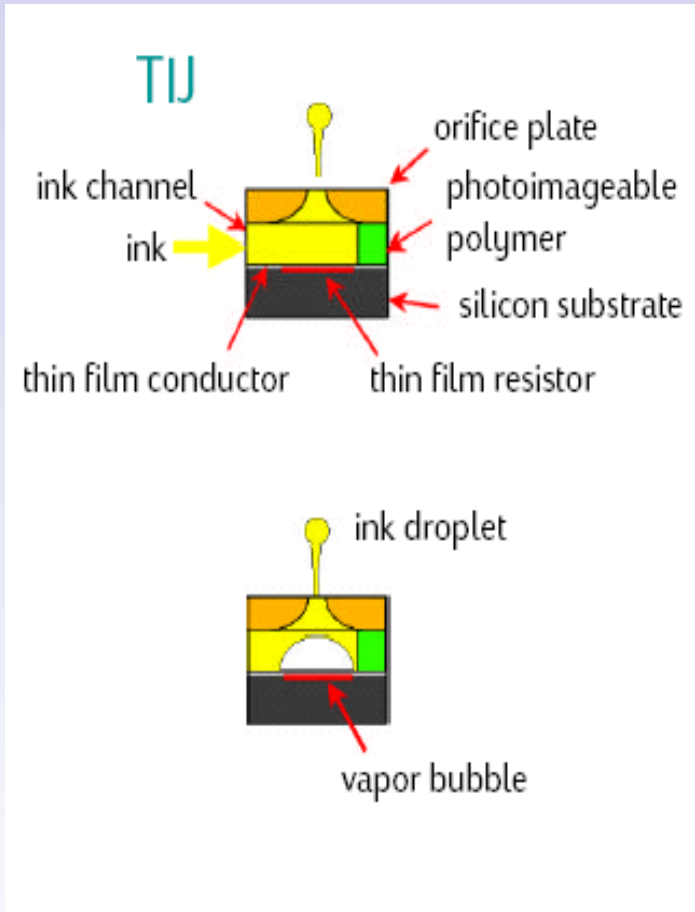
- Can the drop size be controlled?
- Can the spatial spacing of the drops be controlled?
- Can the break-up length be controlled?
- What would be the drop selection method?



❖ Electrostatic Inkjet

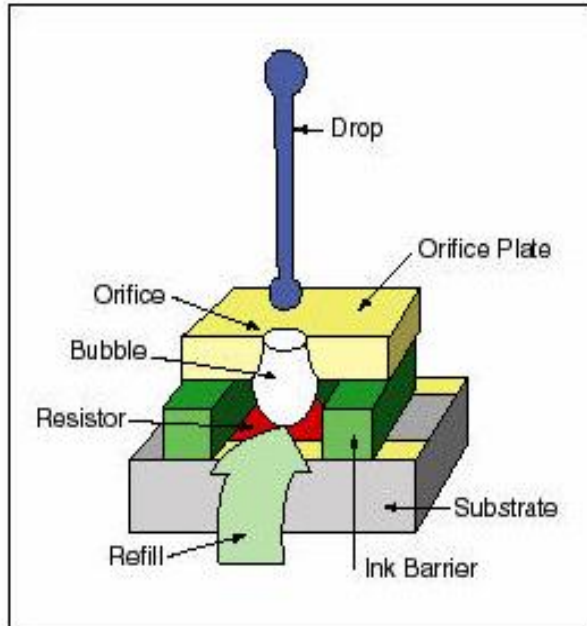


❖ Thermal inkjet



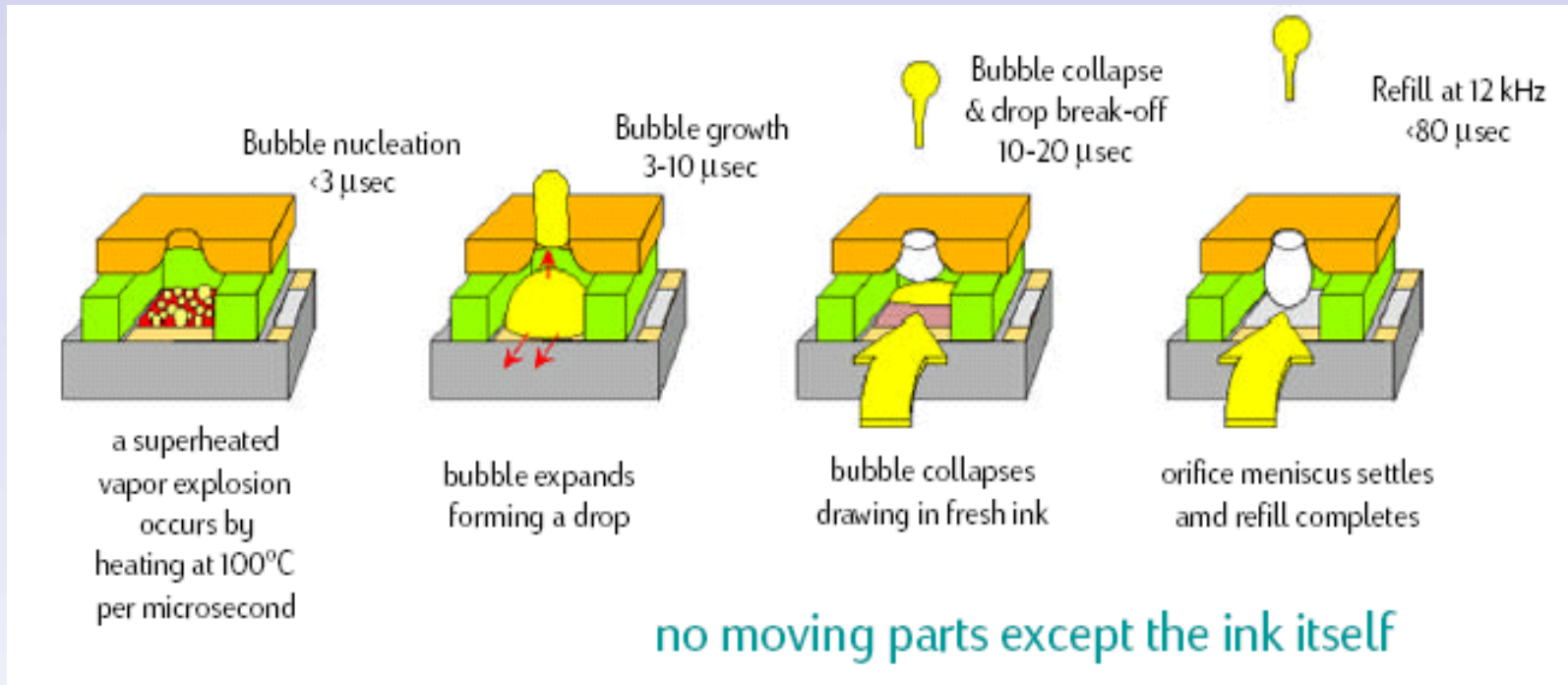
- ❖ **Uses tiny resistor to rapidly heat a thin layer of liquid ink**
- ❖ **Vaporize a tiny fraction of the ink to form an expanding bubble that ejects a droplet (and any trapped air)**
- ❖ **Nothing moves but the ink – very high frequency attainable**
- ❖ **Use fabrication technology similar to semiconductor manufacturing; nozzles can be integrated at very high densities – provides high throughput and spare nozzles for reliability**

❖ Thermal inkjet



- ❖ **Stack of extremely thin films form the floor of each firing chamber, some are electrically conductive, others are insulators.**
- ❖ **Thin film resistor is located in the center of each firing chamber floor and gets extremely hot when electricity passes through**
- ❖ **Each resistor is 60um or smaller on each side, but power density on its surface is 1.28 billion watts per square meter – more than on the surface of the Sun!**

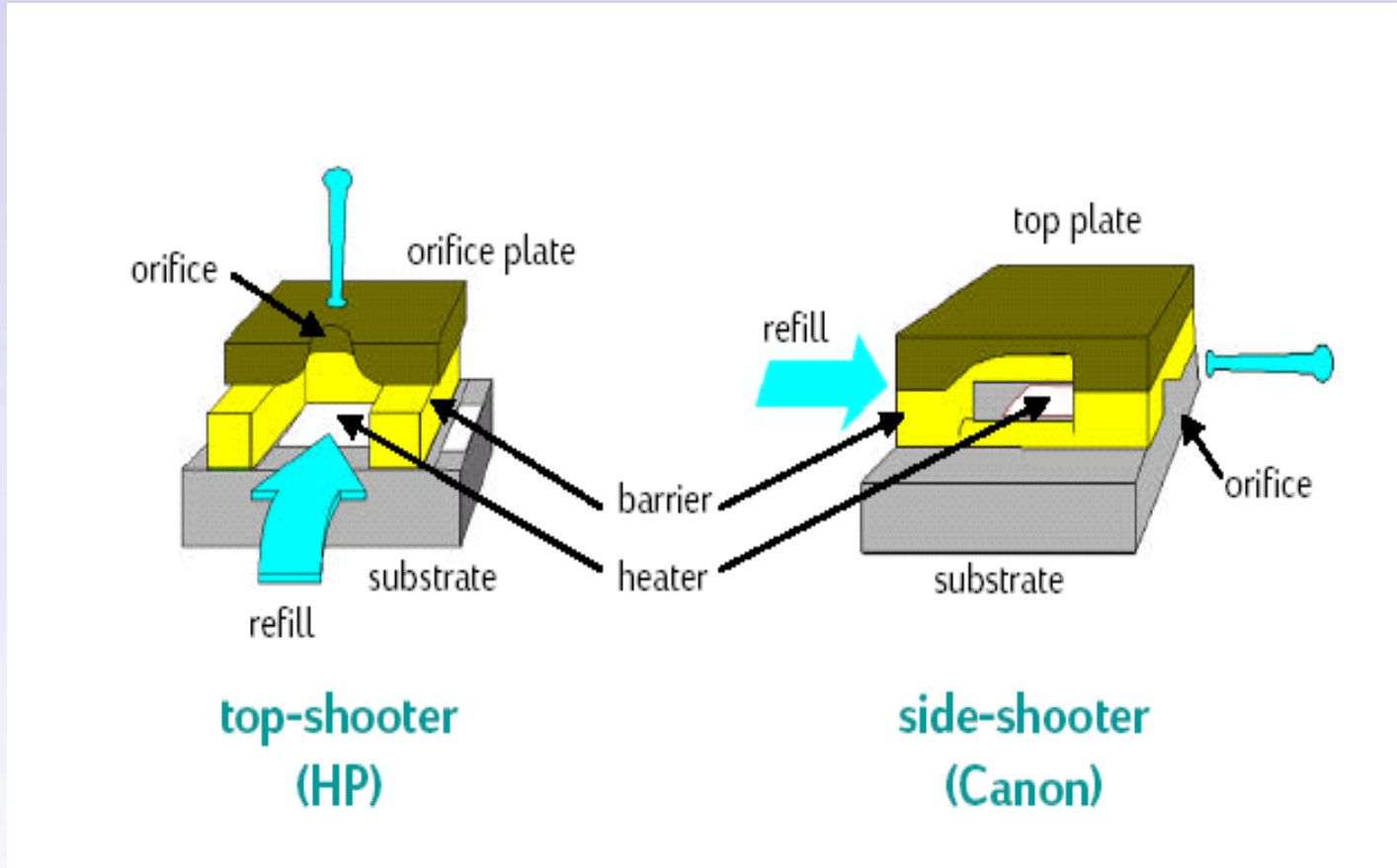
❖ Thermal inkjet



- ❖ A film of ink about 100nm thick is heated to $\sim 340^\circ\text{C}$
- ❖ A vapor bubble forms to expel the ink, but it doesn't "boil"

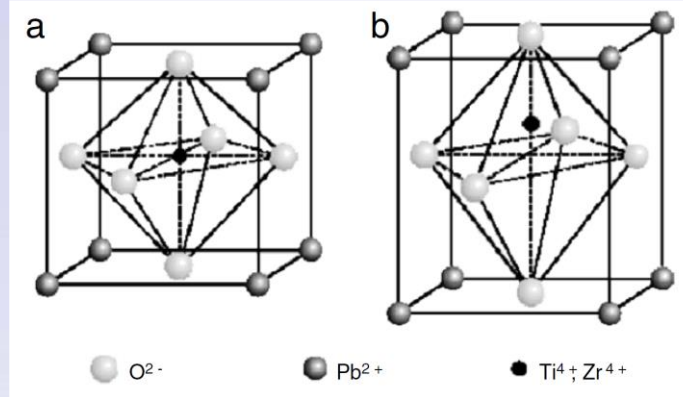
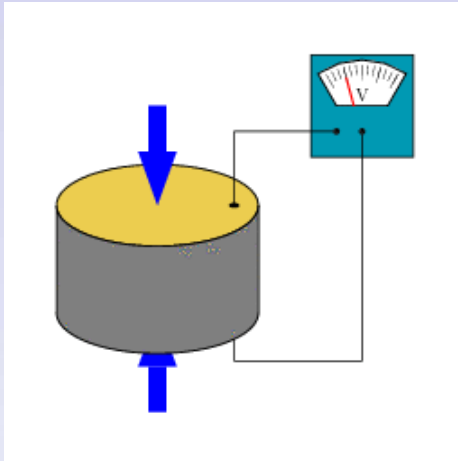
Inkjet Deposition

❖ Thermal inkjet



❖ Piezoelectric Inkjet

Piezoelectricity

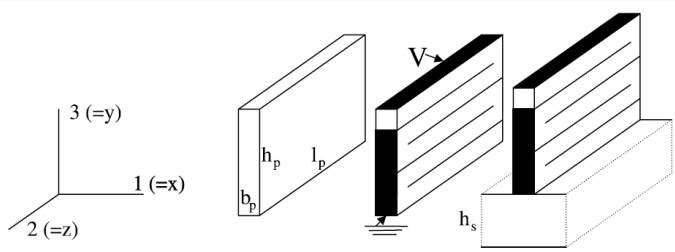


$$\underline{\underline{S}} = \underline{\underline{d}} \underline{\underline{E}}$$

$$\underline{\underline{D}} = \underline{\underline{d}}^T \underline{\underline{T}}$$

- ❖ The elementary cell of PZT: **(a) above the Curie temperature; (b) below the Curie temperature.** At a high temperature, the electric charges coincide in a cubic structure and there is no piezoelectricity. Below the Curie temperature the electric charges do not coincide anymore. This results in piezoelectric effect.
- ❖ **D** is the electric displacement field (or the charge density), **S** is strain, **E** is the applied electrical field, **T** is stress, **d** and **d^T** are matrices for the piezoelectric effects
- ❖ **Caused by lack of symmetry, and therefore inherently anisotropic**

◆ Piezoelectric Inkjet



$$\{S\} = [s^E] \{T\} + [d^t] \{E\}$$

$$\{D\} = [d] \{T\} + [\epsilon^T] \{E\},$$

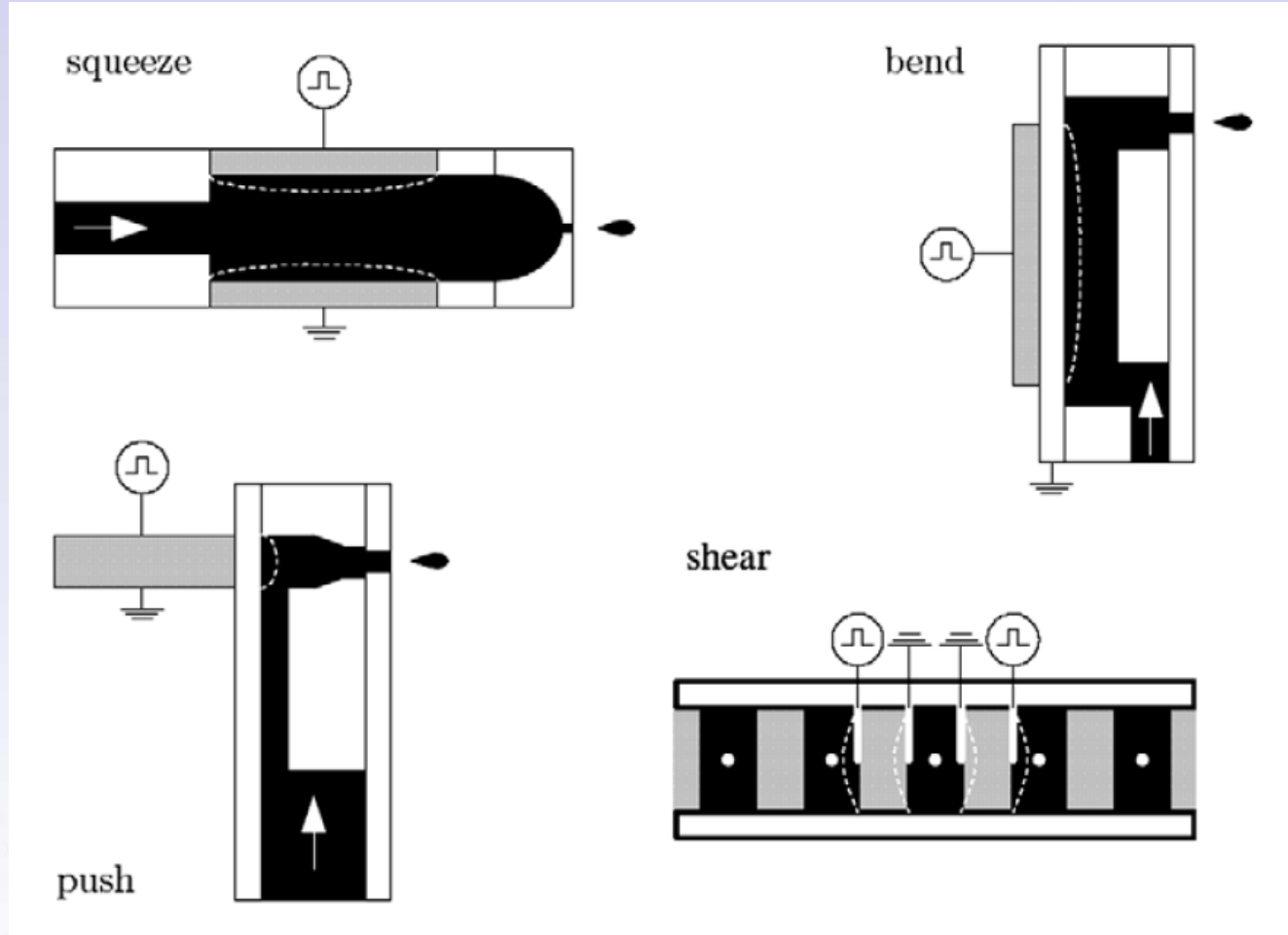
- ◆ s is compliance matrix, characterize mechanical behavior;
- ◆ ϵ is permittivity matrix, characterize electrical behavior;
- ◆ d is the piezoelectric matrix, characterize the coupling effects
- ◆ $\Delta y = d_{33}V$, $d_{33} \approx 0.4\text{nm/V}$ for most piezo materials;
- ◆ For 25 pl droplet with a channel of 10 mm length and a width of 250 mm, the displacement of the piezo element should be 20 nm. This requires a driving voltage of 80 V.

$$\begin{bmatrix} S_1 \\ S_2 \\ S_3 \\ S_4 \\ S_5 \\ S_6 \end{bmatrix} = \begin{bmatrix} s_{11}^E & s_{12}^E & s_{13}^E & 0 & 0 & 0 \\ s_{21}^E & s_{22}^E & s_{23}^E & 0 & 0 & 0 \\ s_{31}^E & s_{32}^E & s_{33}^E & 0 & 0 & 0 \\ 0 & 0 & 0 & s_{44}^E & 0 & 0 \\ 0 & 0 & 0 & 0 & s_{55}^E & 0 \\ 0 & 0 & 0 & 0 & 0 & s_{66}^E \end{bmatrix} \begin{bmatrix} T_1 \\ T_2 \\ T_3 \\ T_4 \\ T_5 \\ T_6 \end{bmatrix} + \begin{bmatrix} 0 & 0 & d_{31} \\ 0 & 0 & d_{32} \\ 0 & 0 & d_{33} \\ 0 & d_{24} & 0 \\ d_{15} & 0 & 0 \\ 0 & 0 & 0 \end{bmatrix} \begin{bmatrix} E_1 \\ E_2 \\ E_3 \end{bmatrix}$$

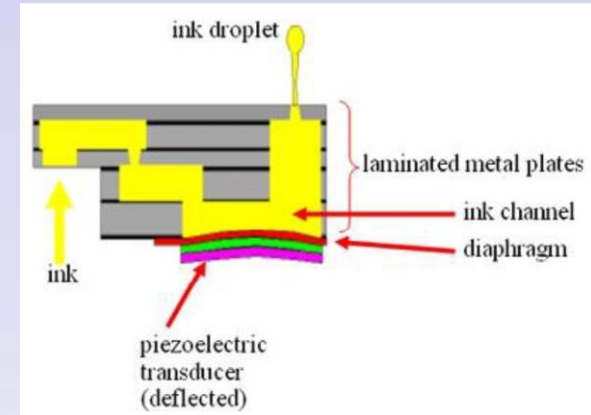
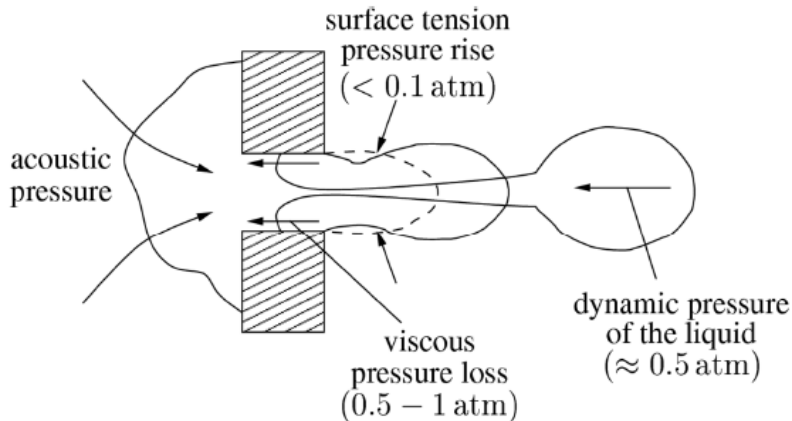
$s_{66}^E = 2(s_{11}^E - s_{12}^E)$

$$\begin{bmatrix} D_1 \\ D_2 \\ D_3 \end{bmatrix} = \begin{bmatrix} 0 & 0 & 0 & 0 & d_{15} & 0 \\ 0 & 0 & 0 & d_{24} & 0 & 0 \\ d_{31} & d_{32} & d_{33} & 0 & 0 & 0 \end{bmatrix} \begin{bmatrix} T_1 \\ T_2 \\ T_3 \\ T_4 \\ T_5 \\ T_6 \end{bmatrix} + \begin{bmatrix} \epsilon_{11} & 0 & 0 \\ 0 & \epsilon_{22} & 0 \\ 0 & 0 & \epsilon_{33} \end{bmatrix} \begin{bmatrix} E_1 \\ E_2 \\ E_3 \end{bmatrix}$$

❖ Piezoelectric Inkjet



❖ Piezoelectric Inkjet

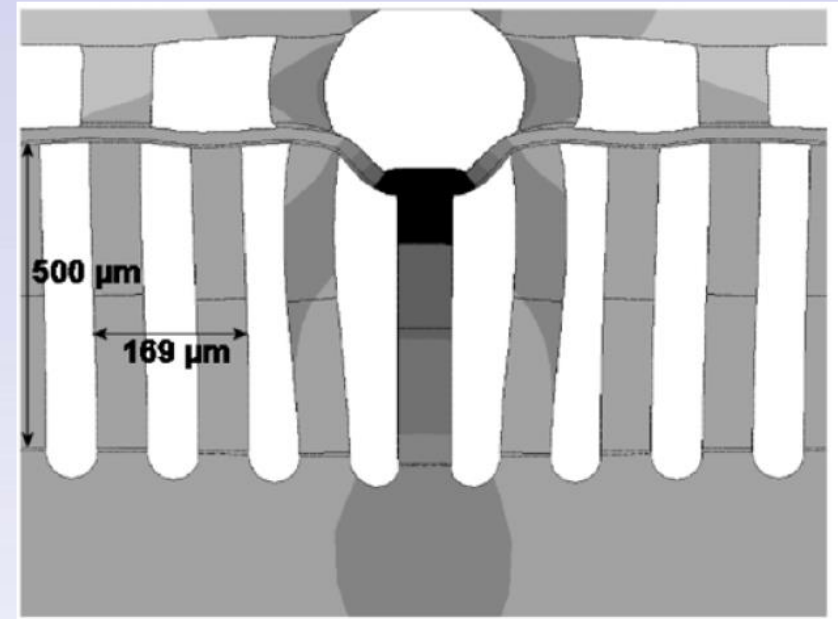
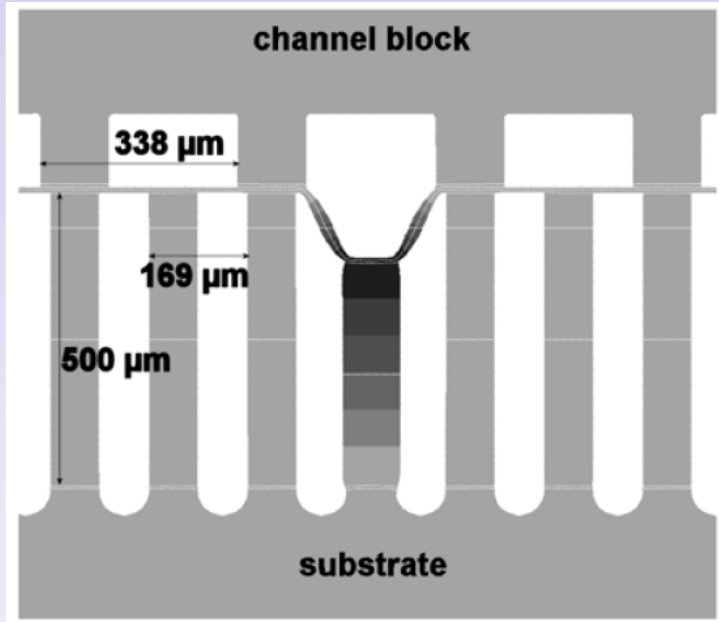


❖ Actuation efficiency

- ❖ **Piezo (electrical to mechanical): ~15% to 25%**
- ❖ **Piezo deformation to channel deformation: ~13%**
- ❖ **Channel deformation to acoustic pressure wave: ~20%**
- ❖ **Acoustic pressure to droplet (for low viscosity): ~10%**
- ❖ **Total efficiency: ~0.07%**
- ❖ **For a 32pL droplet with a ejection velocity of 7m/s, the surface energy and kinetic energy of the droplet is ~0.85 nJ. As a result, the required input of electric energy is 1200 nJ.**
- ❖ **For an operation frequency of 100 kHz (10us), the required power is then 0.12W. For a voltage of 40V, current 3mA.**

Inkjet Deposition

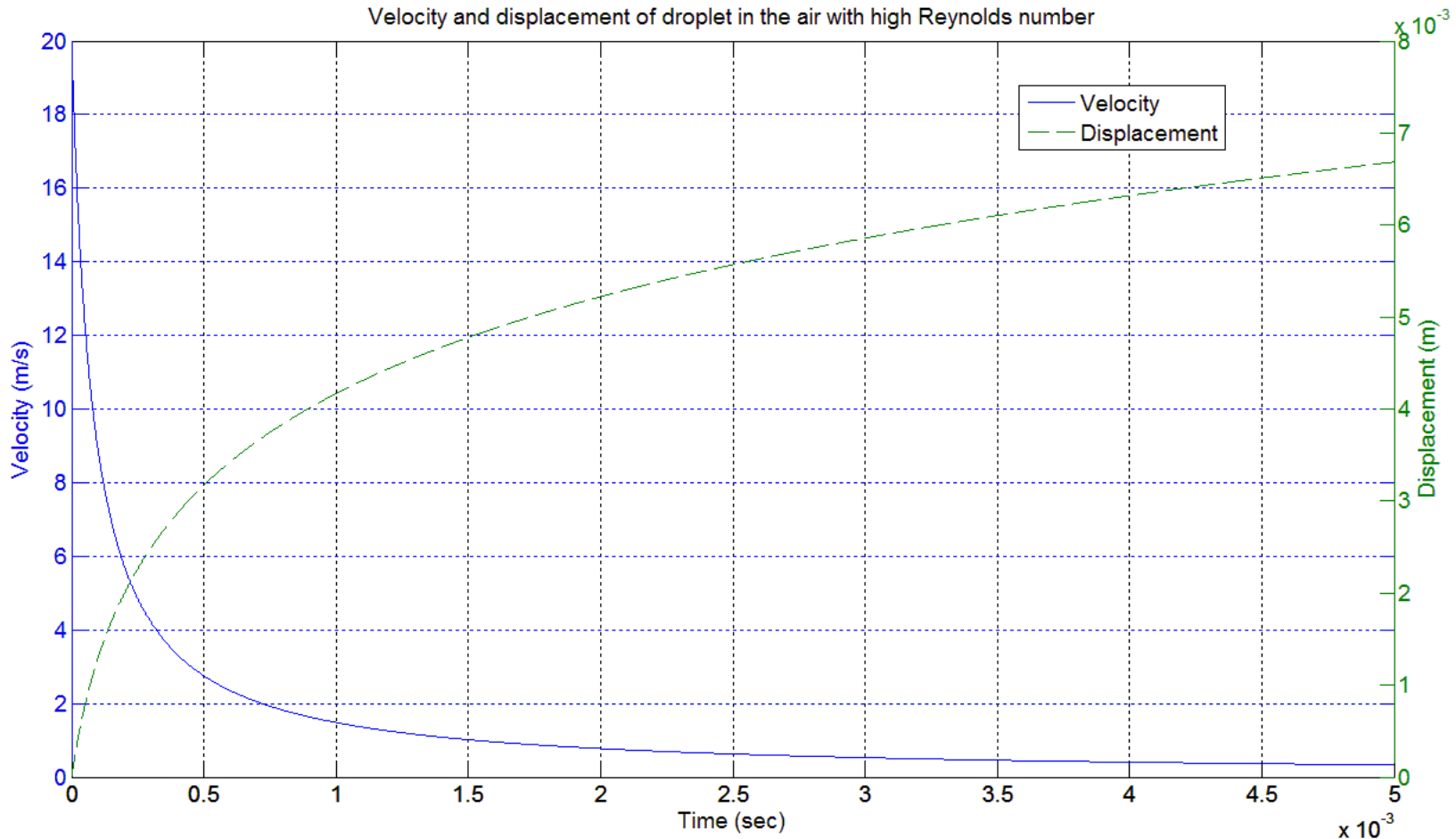
◆ Piezoelectric Inkjet



Cross talk



◆ Droplet falling in the air



$$\vec{F}_g - \vec{F}_v - \vec{F}_d = 0$$

$$\vec{F}_d = -b \vec{v}$$

Low speed

$$\vec{F}_d = -\frac{1}{2} \rho \vec{v}^2 AC_d$$

High speed

Inkjet

Overview

Complexity

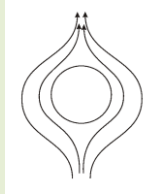
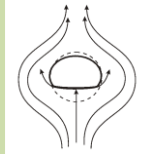
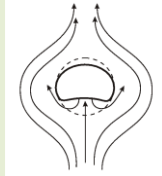
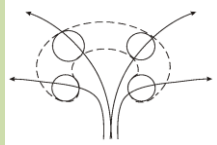
Printhead

Falling

Deposition

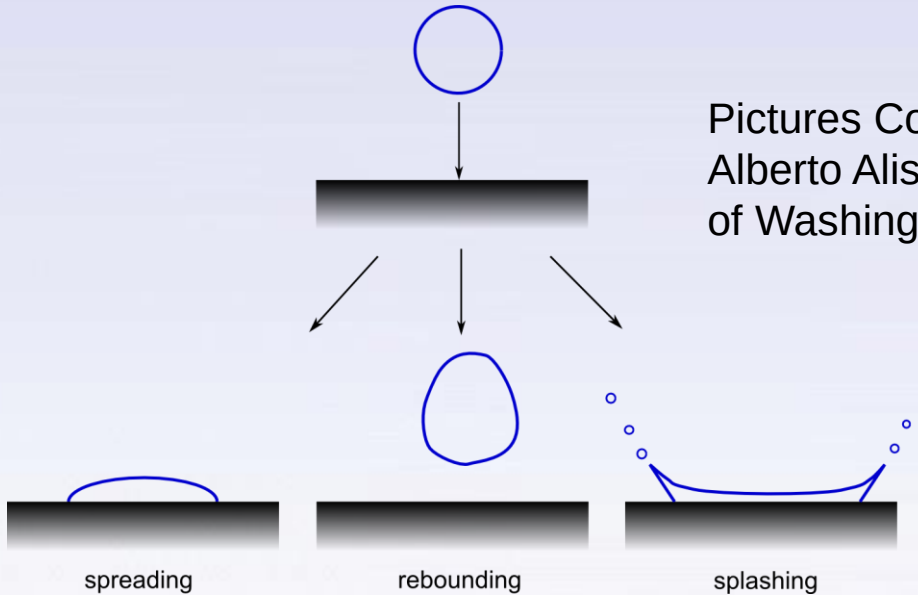
Drying

❖ Droplet falling in the air

	Drop size	Characteristic shape
Surface-tension forces are able to maintain the spherical shape against external forces.	0.14 mm	
A very slight shortening of the vertical axis and the drop is an "oblate spheroid". The vertical axis is about 98% of the horizontal axis.	0.50 mm	
Flattening of bases begins.	1.4 mm	
Concavity of the flattened base begins.	2 mm	
At 5 mm the force of the air through which the drop is falling causes the drop to break up.	5mm	

Raindrop falling in the air

❖ Droplet deposition



Pictures Courtesy Dr.
Alberto Aliseda at University
of Washington

Inkjet

Overview

Complexity

Printhead

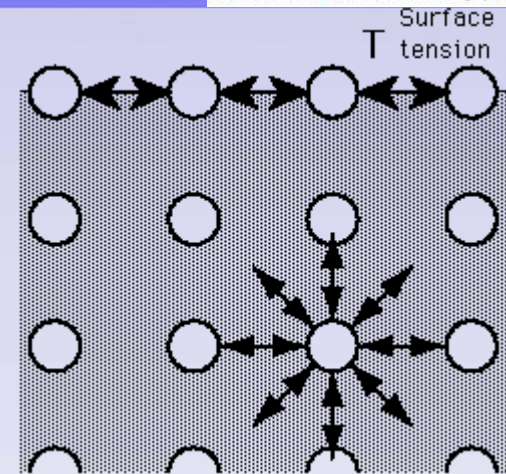
Falling

Deposition

Drying

❖ Droplet deposition

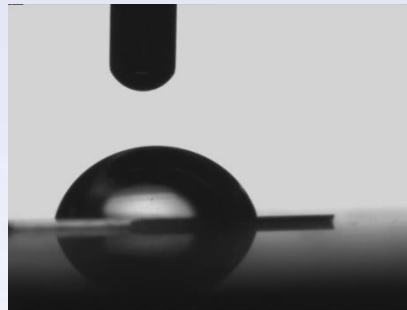
❖ Wetting on a solid surface



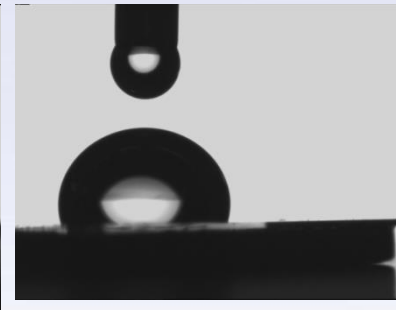
Reason for Surface tension



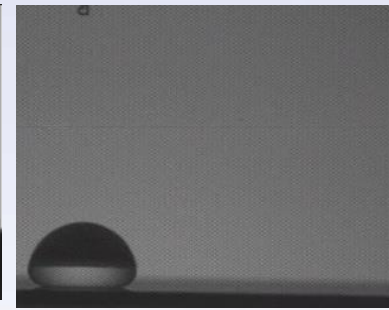
Total wetting



Partial wetting



Partial non-wetting



Non-wetting

Inkjet

Overview

Complexity

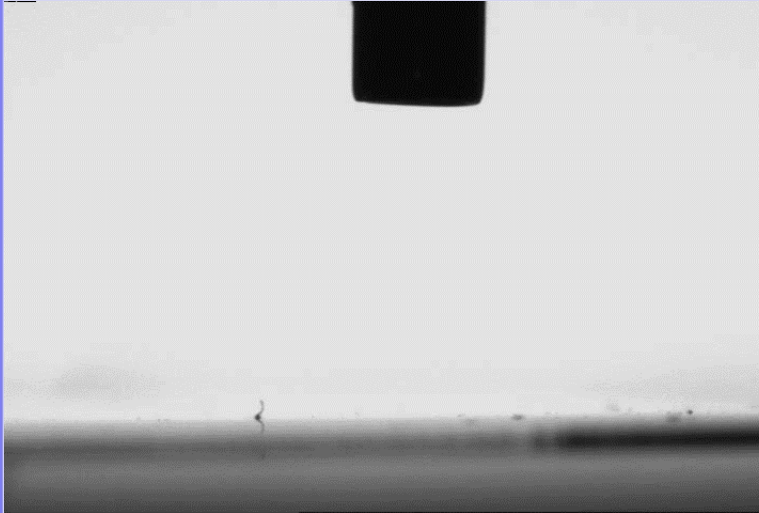
Printhead

Falling

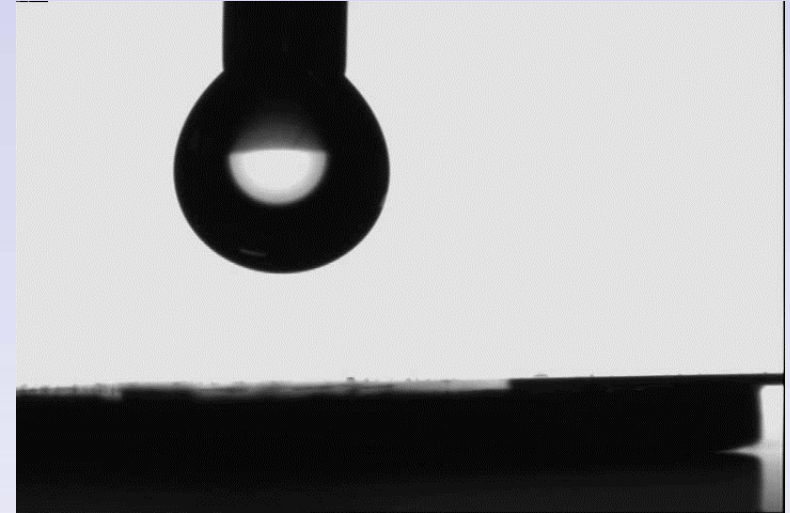
Deposition

Drying

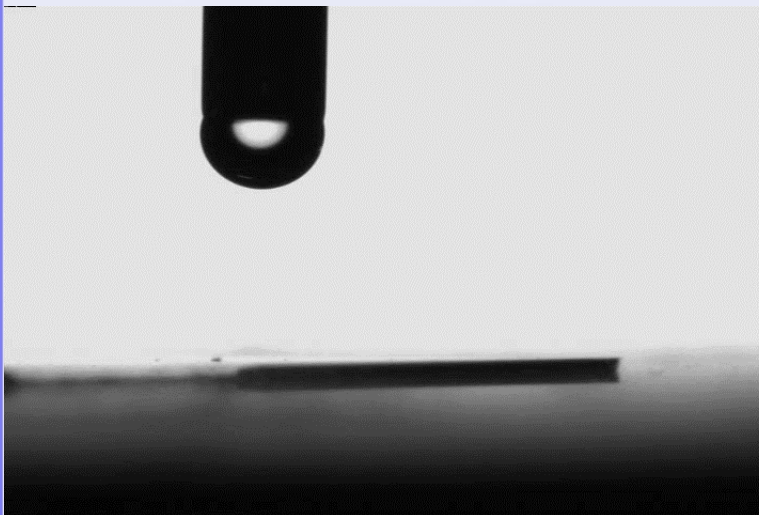
◆ Droplet deposition – different wetting



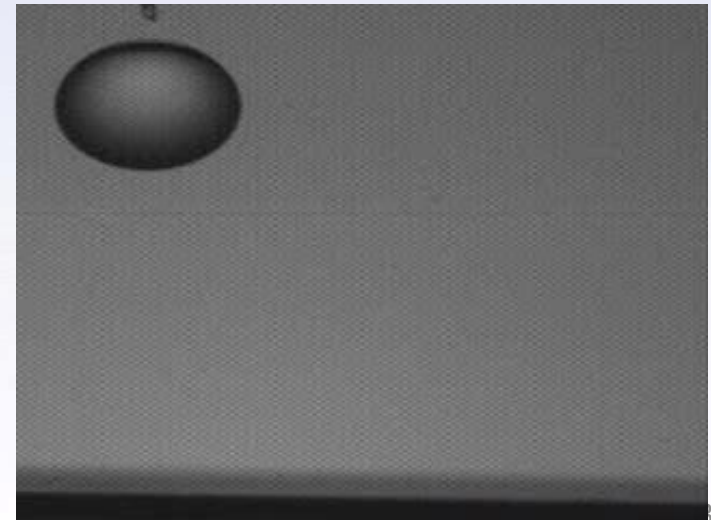
Hydrophilic



Hydrophobic



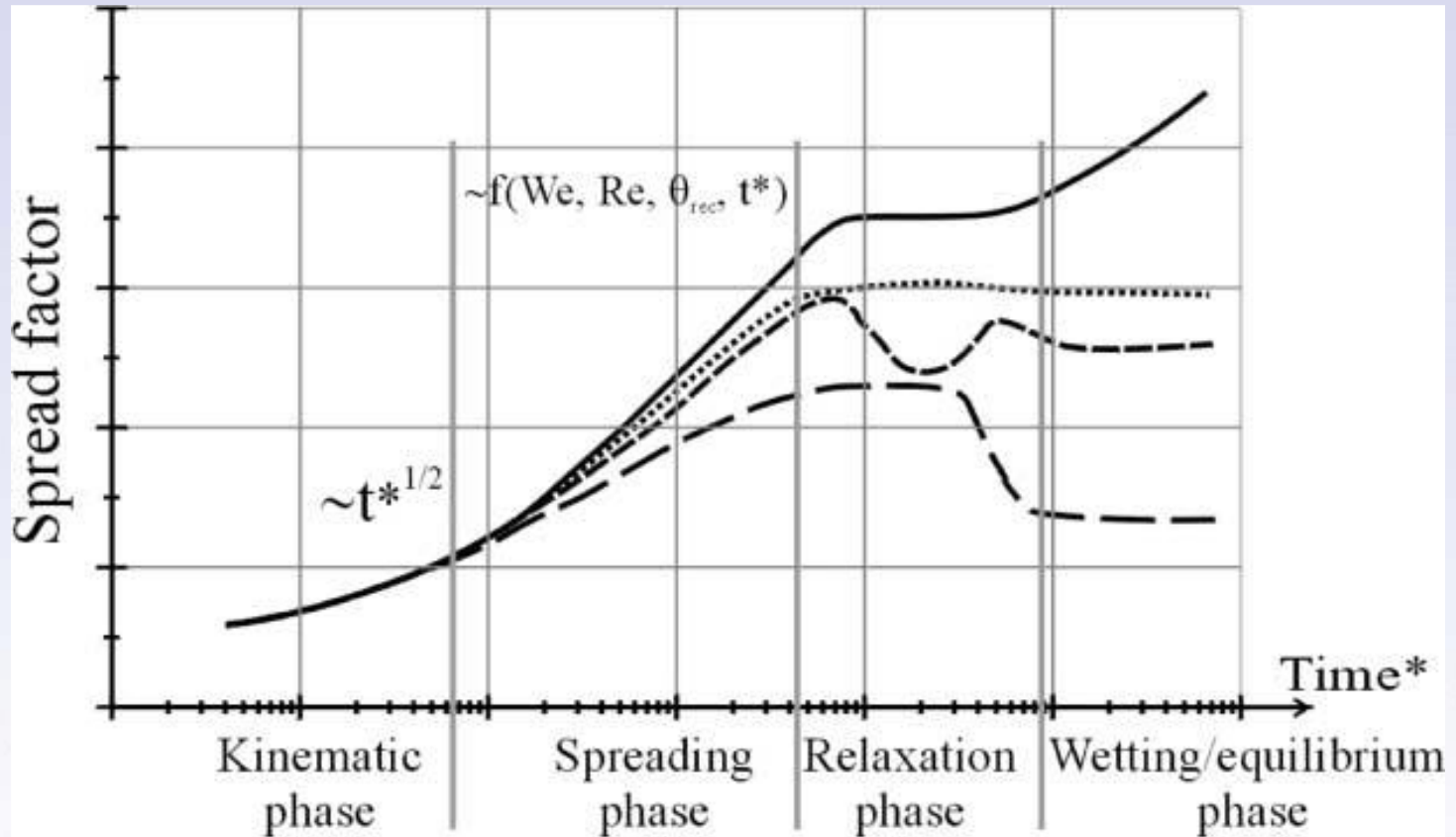
Partial Wetting



Ultra-hydrophobic

◆ Droplet deposition

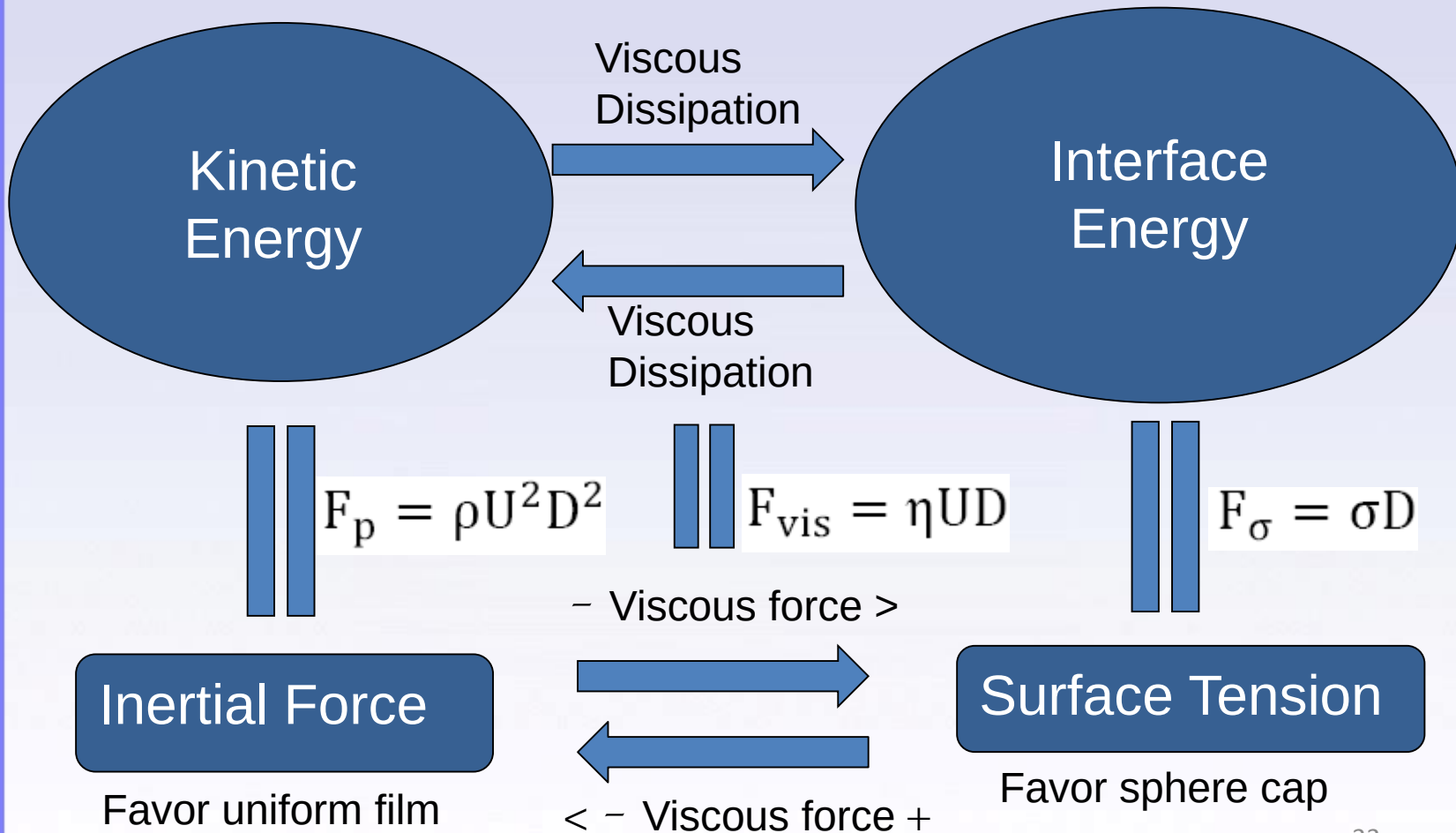
◆ Droplet spreading dynamics



Schematic representation of the spread factor with time

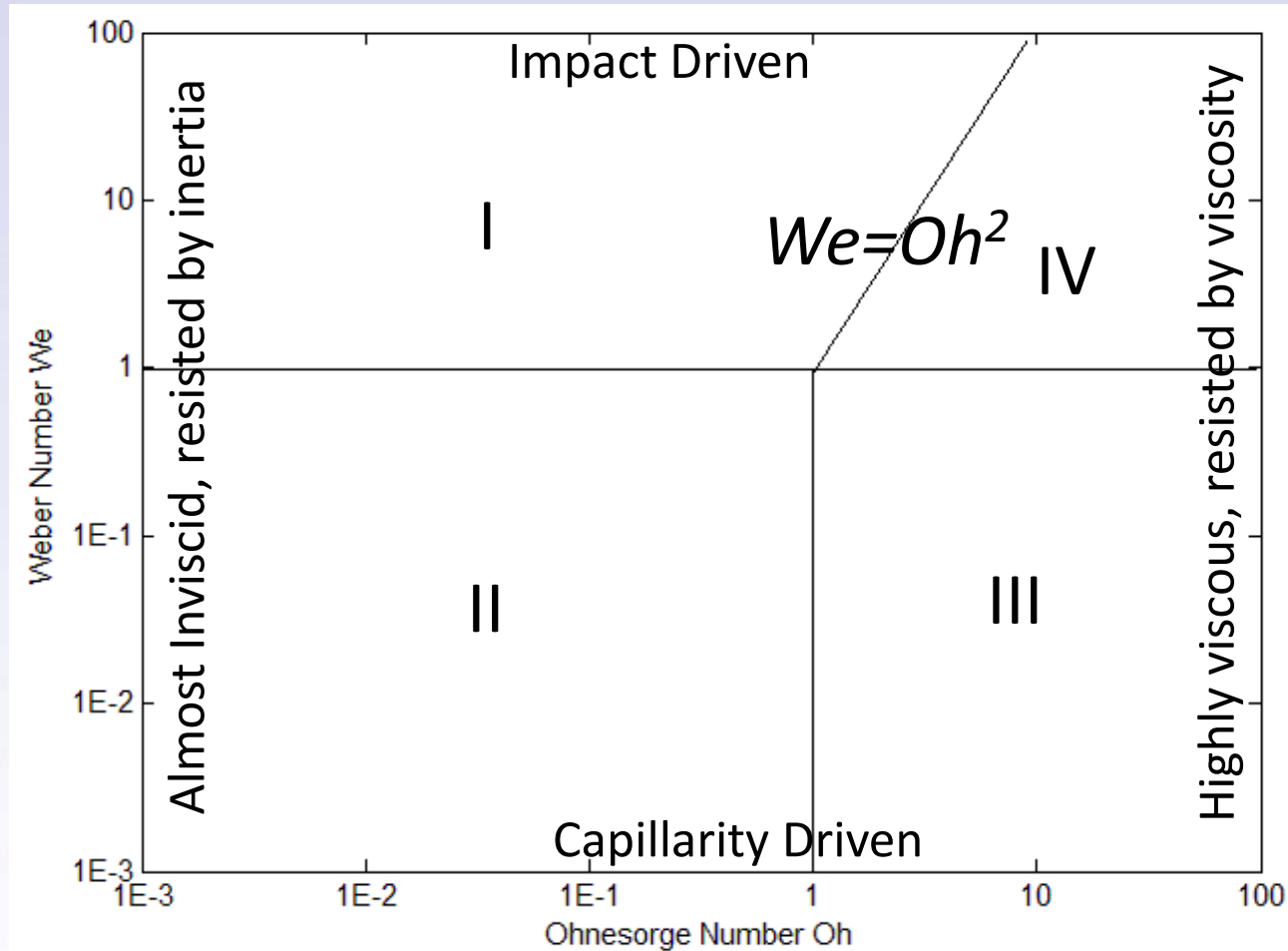
❖ Droplet deposition

❖ Physics of droplet spreading dynamics



◆ Droplet deposition

◆ Regimes of droplet spreading dynamics



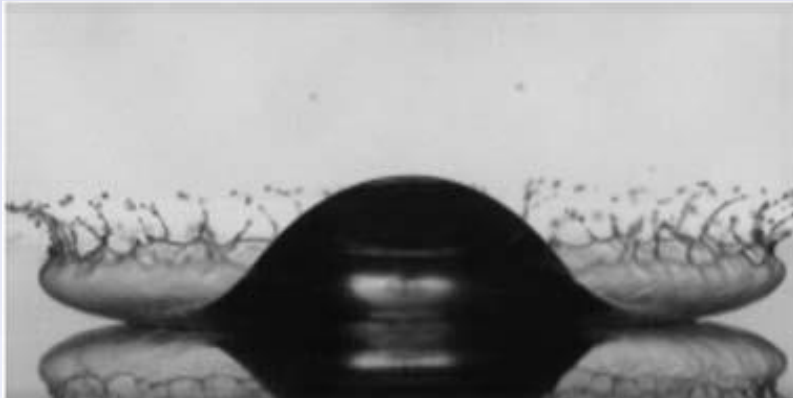
Impact Regime

◆ Droplet deposition

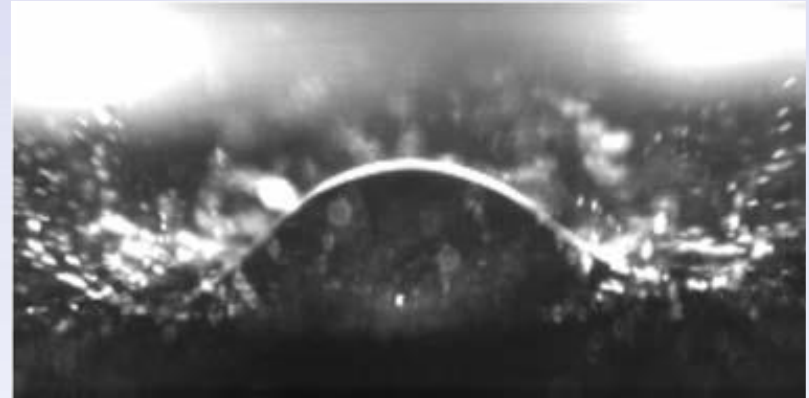
◆ Splash

◆ Corona splash

◆ Prompt splash



Caused by surrounding gas

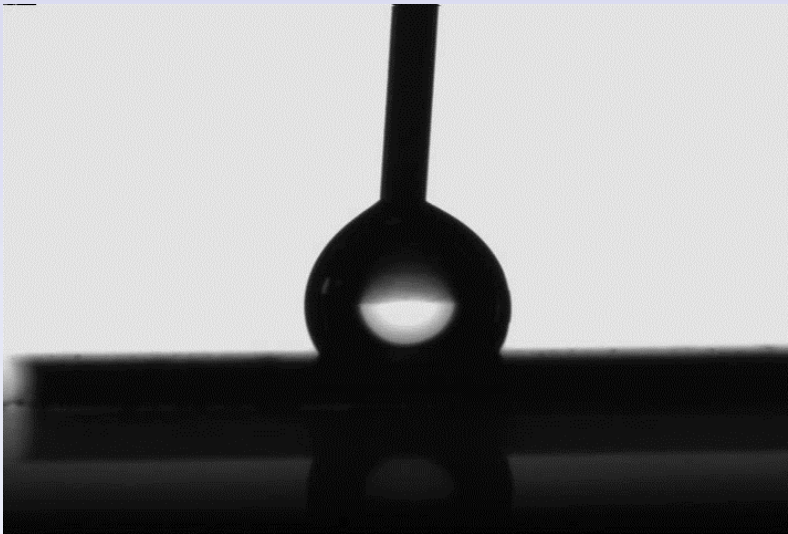


Caused by rough surface

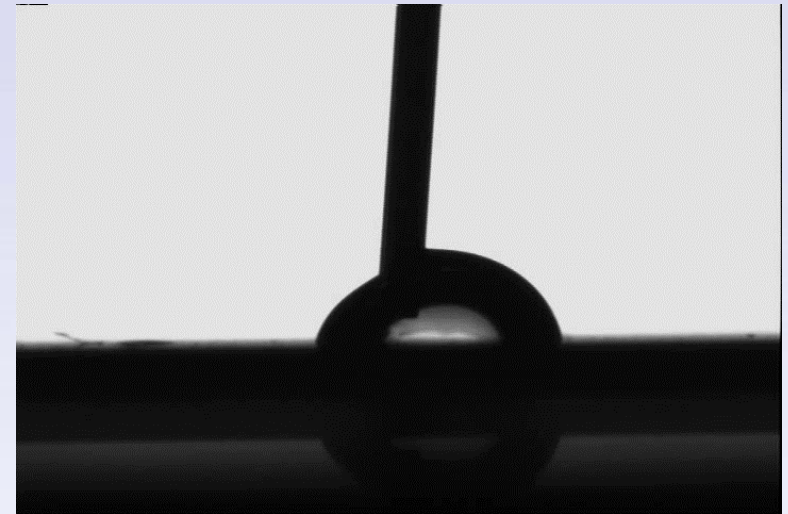


◆ Droplet deposition

◆ Contact angle hysteresis



Advancing contact angle



Receding contact angle

Inkjet

Overview

Complexity

Printhead

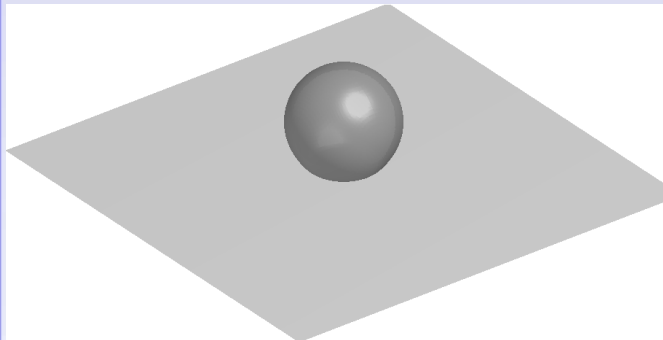
Falling

Deposition

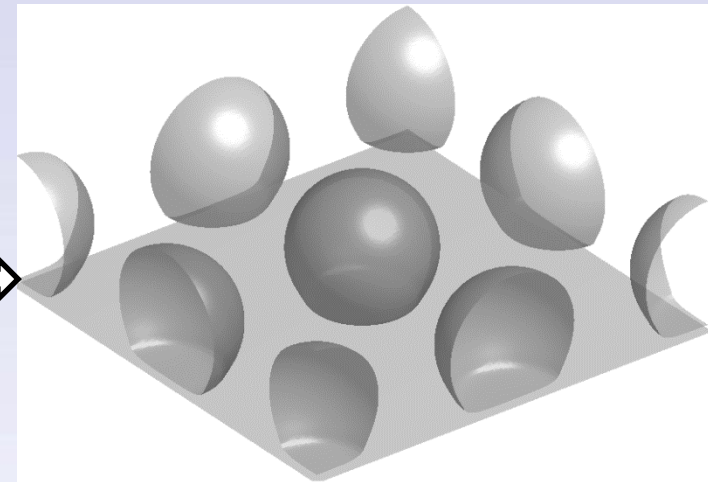
Drying

❖ Droplet deposition

❖ Simulations of droplet impingement dynamics



3D



Most previous research: single droplet impact
due to prohibitive computational complexity
and cost

Make it more relevant to manufacturing, we
need to study multiple droplet interaction

◆ Droplet deposition

◆ Simulations of droplet impingement dynamics – Lattice Boltzmann method

Re: 238.26

We: 12.88

Fluid: Water

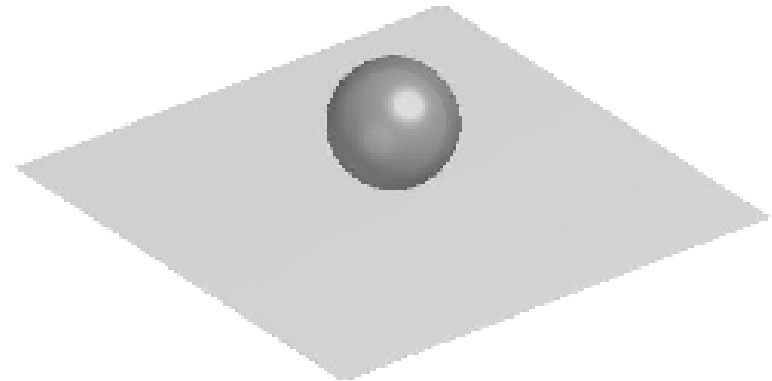
Droplet size: 48.8 μ m

Density: 1e3 kg/m³

Impact velocity: 4.36m/s

Viscosity: 8.93e-4Pa*s

Surface tension: 0.072N/m



COMSOL on a cluster

CPU: 16-core

Memory: Over 100GB

Time: Over a month

VS

Our LBM on a Laptop

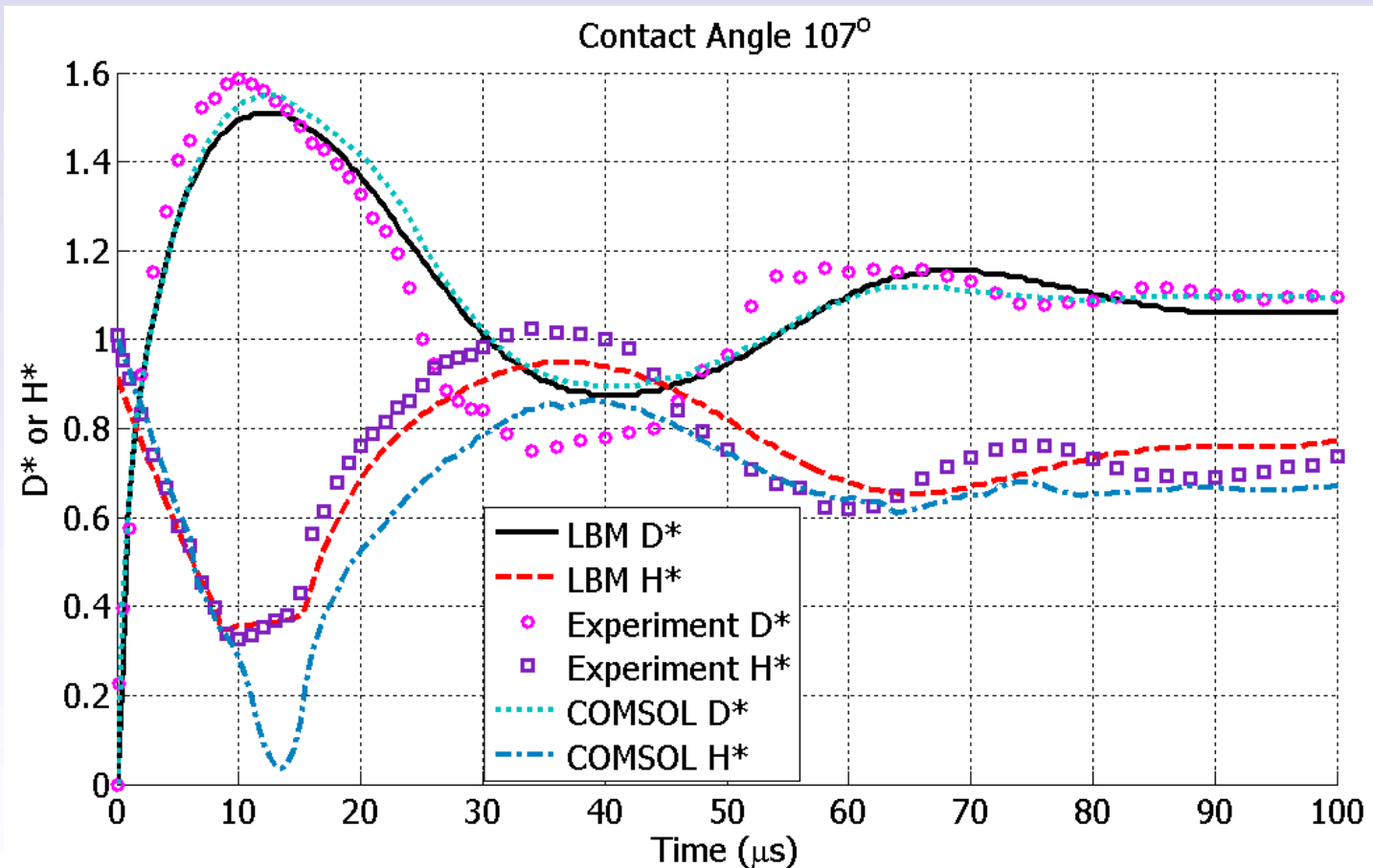
CPU: single thread

Memory: ~ 1GB

Time: Less than 20 hrs

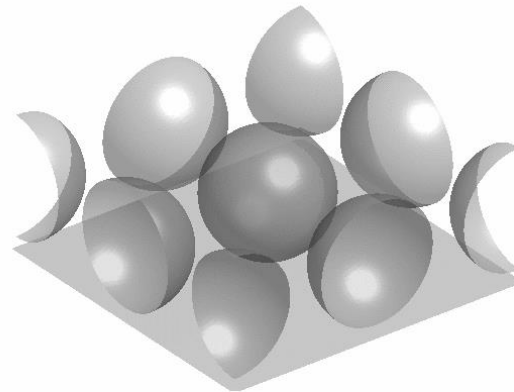
◆ Droplet deposition

◆ Simulations of droplet impingement dynamics – Lattice Boltzmann method – validation



❖ Droplet deposition

❖ Multiple droplet interaction

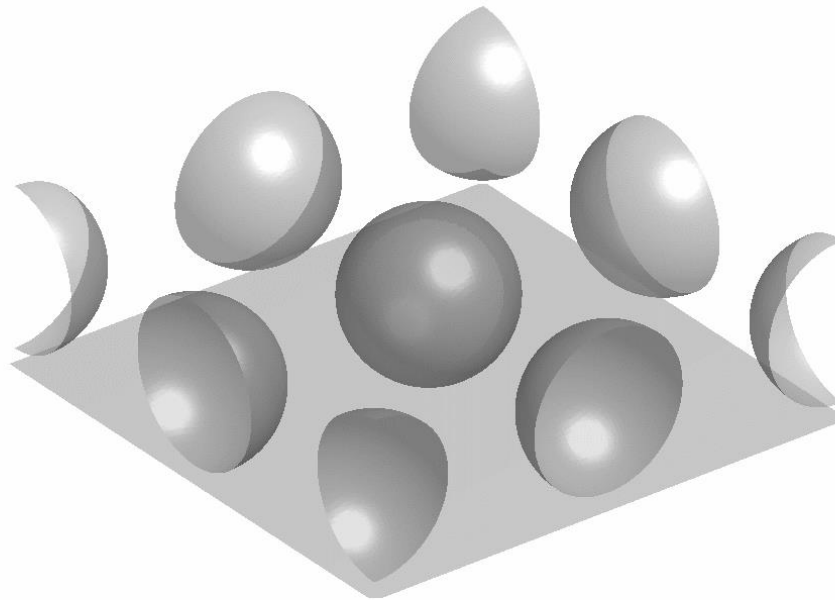


Droplet spacing = $0.3 \times \text{Droplet Diameter}$

Regime I: $We = 100$; $Oh = 0.04$; High impact velocity and low viscosity

❖ Droplet deposition

❖ Multiple droplet interaction

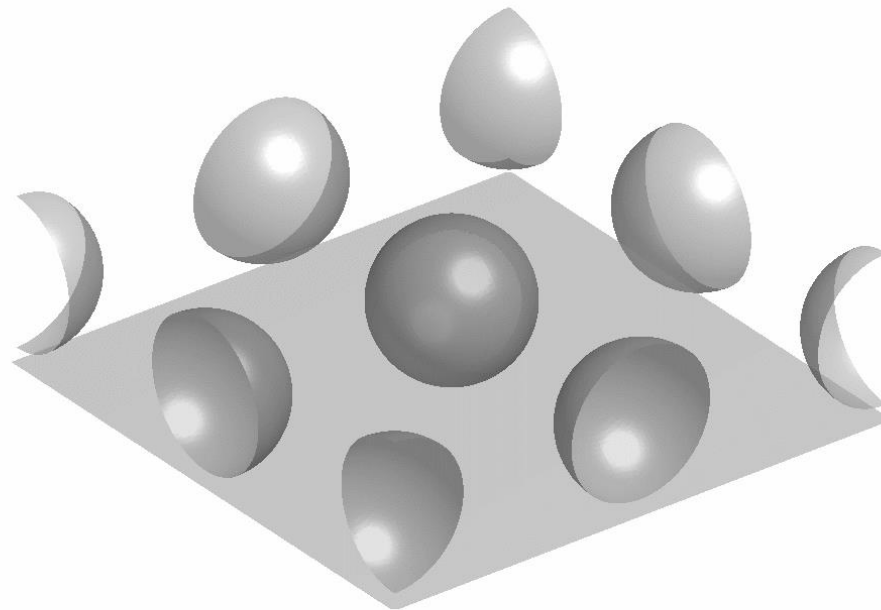


Droplet spacing = $0.6 \times \text{Droplet Diameter}$

Regime I: $We = 100$; $Oh = 0.04$; High impact velocity and low viscosity

❖ Droplet deposition

❖ Multiple droplet interaction

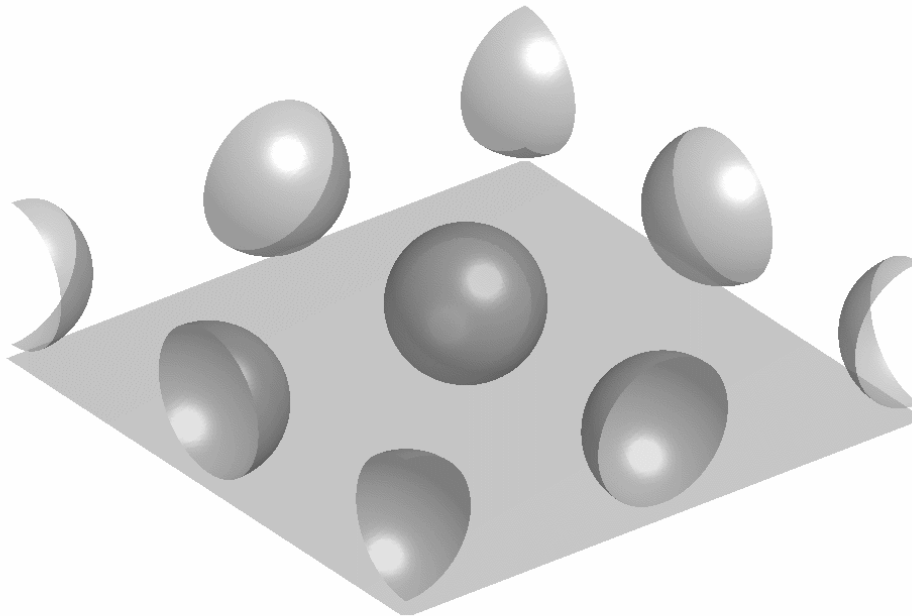


Droplet spacing = $0.8 \times \text{Droplet Diameter}$

Regime I: $We = 100$; $Oh = 0.04$; High impact velocity and low viscosity

❖ Droplet deposition

❖ Multiple droplet interaction

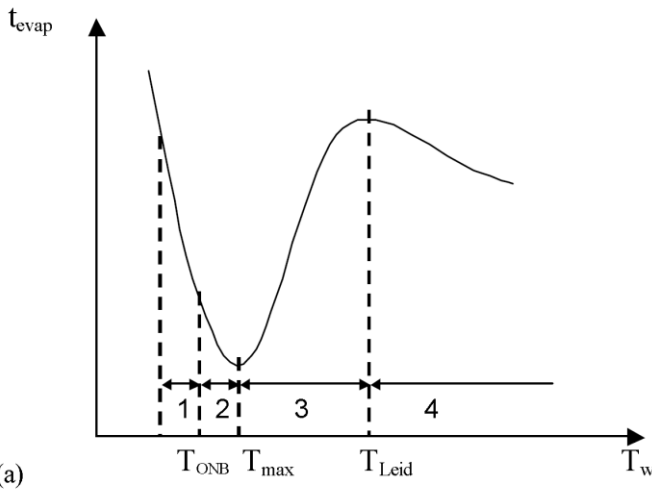


Droplet spacing = $1.0 \times \text{Droplet Diameter}$

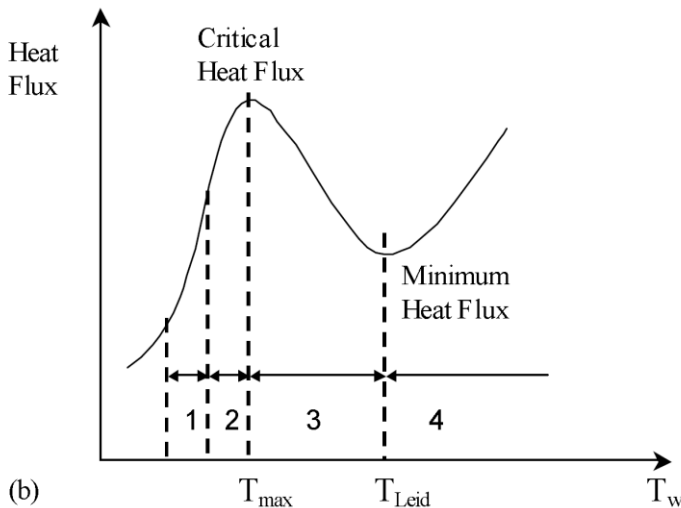
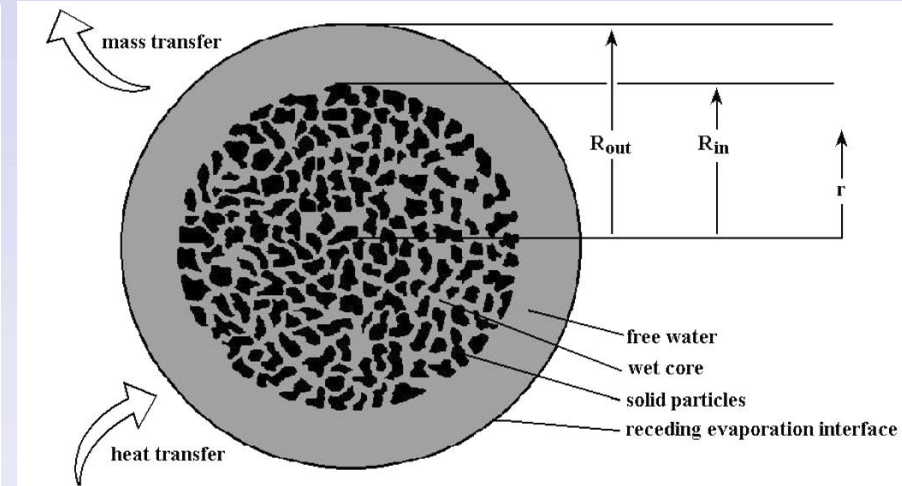
Regime I: $We = 100$; $Oh = 0.04$; High impact velocity and low viscosity

◆ Droplet deposition

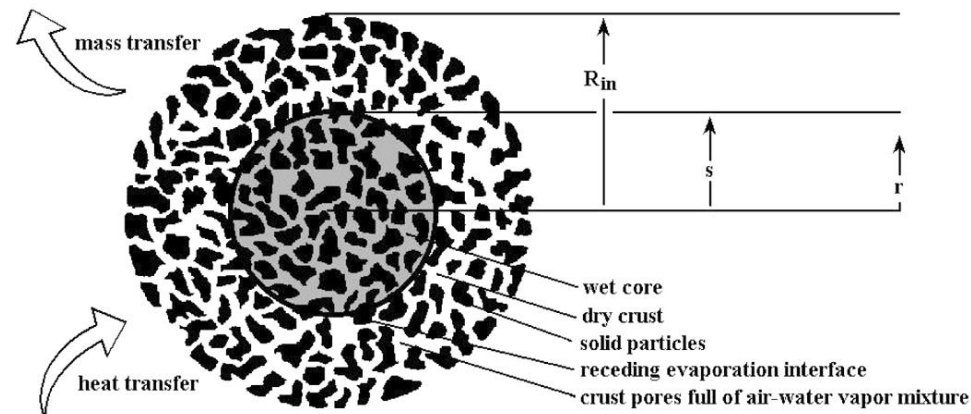
◆ Suspension droplet drying



(a)



(b)



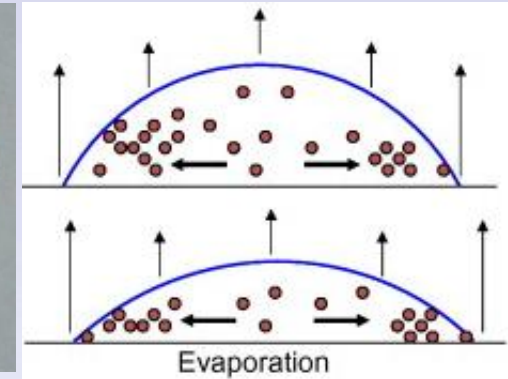
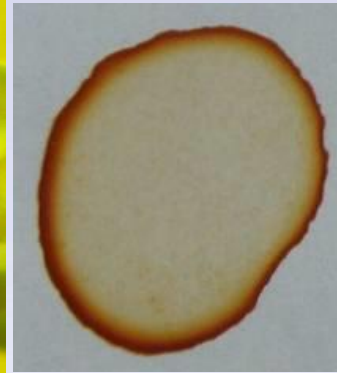
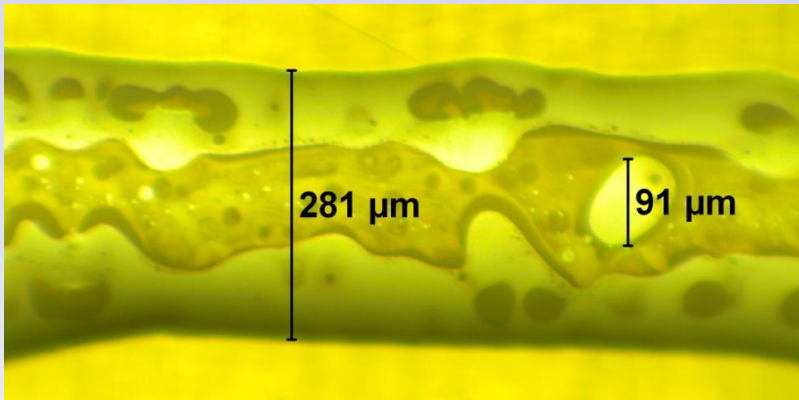
◆ Droplet deposition

◆ Suspension droplet drying

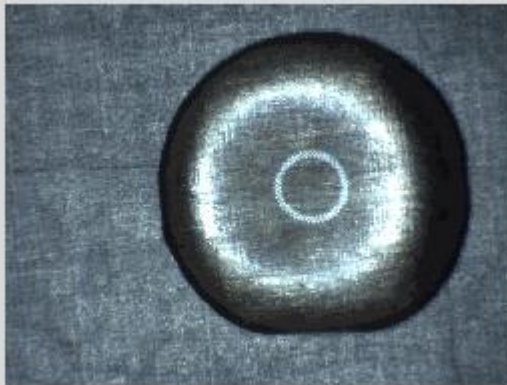
Zone	Regime	Superheat	Description
1	Film evaporation	Low	- When $T_w < T_{ONB}$, the droplet spreads and evaporates slowly - Total contact of the droplet with the surface - Conduction is the dominant mechanism inside the droplet
2	Nucleate boiling	Intermediate	- When $T_{ONB} \leq T_w \leq T_{max}$, vapor bubbles arise in the droplet - Increase in momentum transport around the droplet causes increase of heat transfer - Partial and intermittent contact of the droplets and solid surface
3	Transition boiling	Intermediate	- When $T_{max} < T_w \leq T_{Leid}$, the frequency of contact of the droplet and solid surface decreases, causing a decrease in heat transfer - Formation of an unstable vapor film between droplet and solid surface
4	Film boiling	High	- When $T_w > T_{Leid}$, a thin and stable vapor film is present - No contact between the liquid and solid surface

◆ Droplet deposition

◆ Suspension droplet drying – coffee ring effect



Cracks in the printed line – not conductive Coffee ring effect: evaporation flow



8x faster

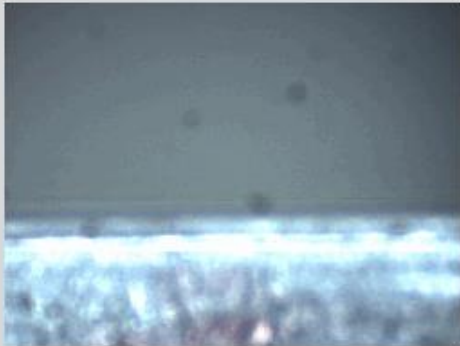


Contact line pinned – form a ring

Contact line moving – no ring

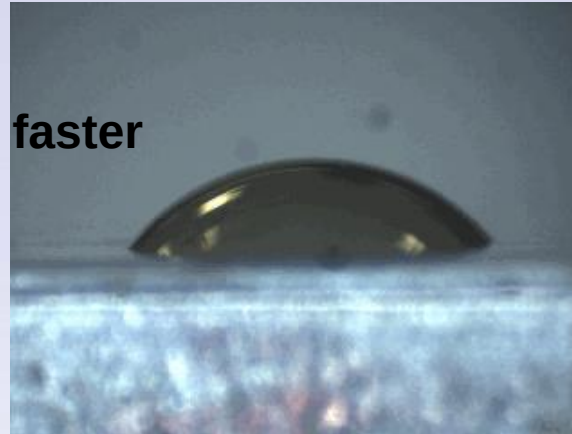
◆ Droplet deposition

◆ Suspension droplet drying – skinning effect



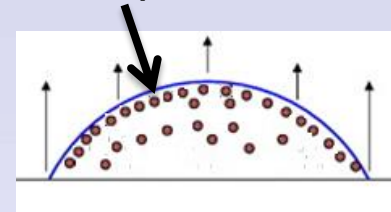
Water on substrate

90x faster



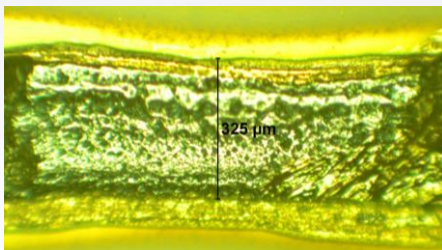
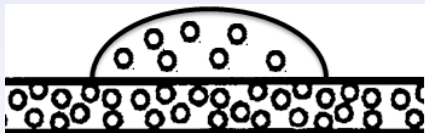
NovaCentrix ink on substrate

Nanoparticle skin

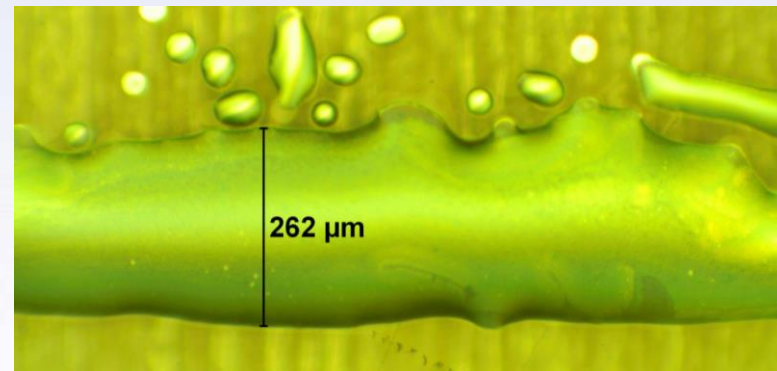


Form a skin on top of the surface, prevent further drying

◆ Possible solutions



Porous substrate:
change evaporation flow



Larger particle size and high viscosity:
reduce particle motion

